

FIG.1

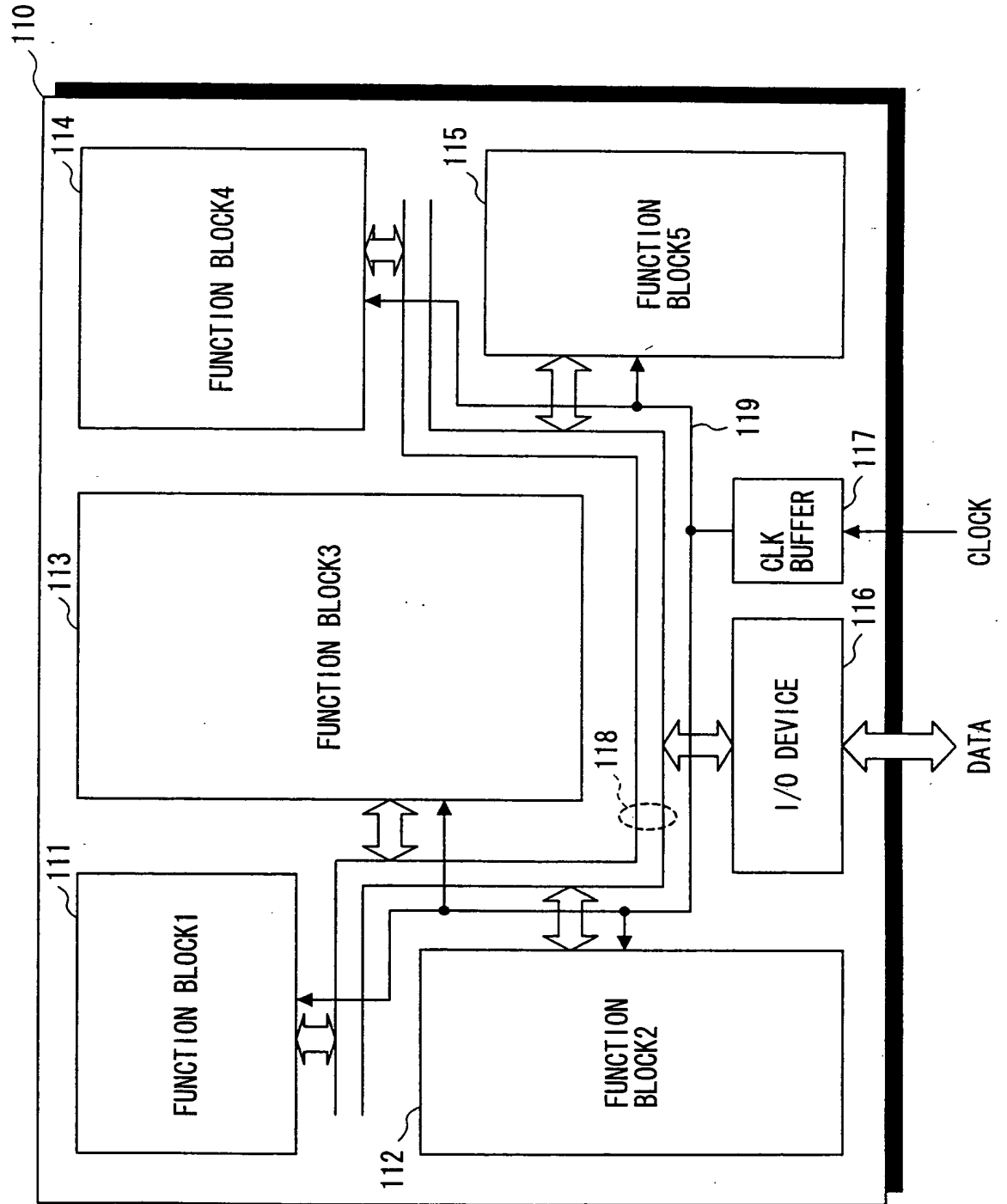


FIG.2

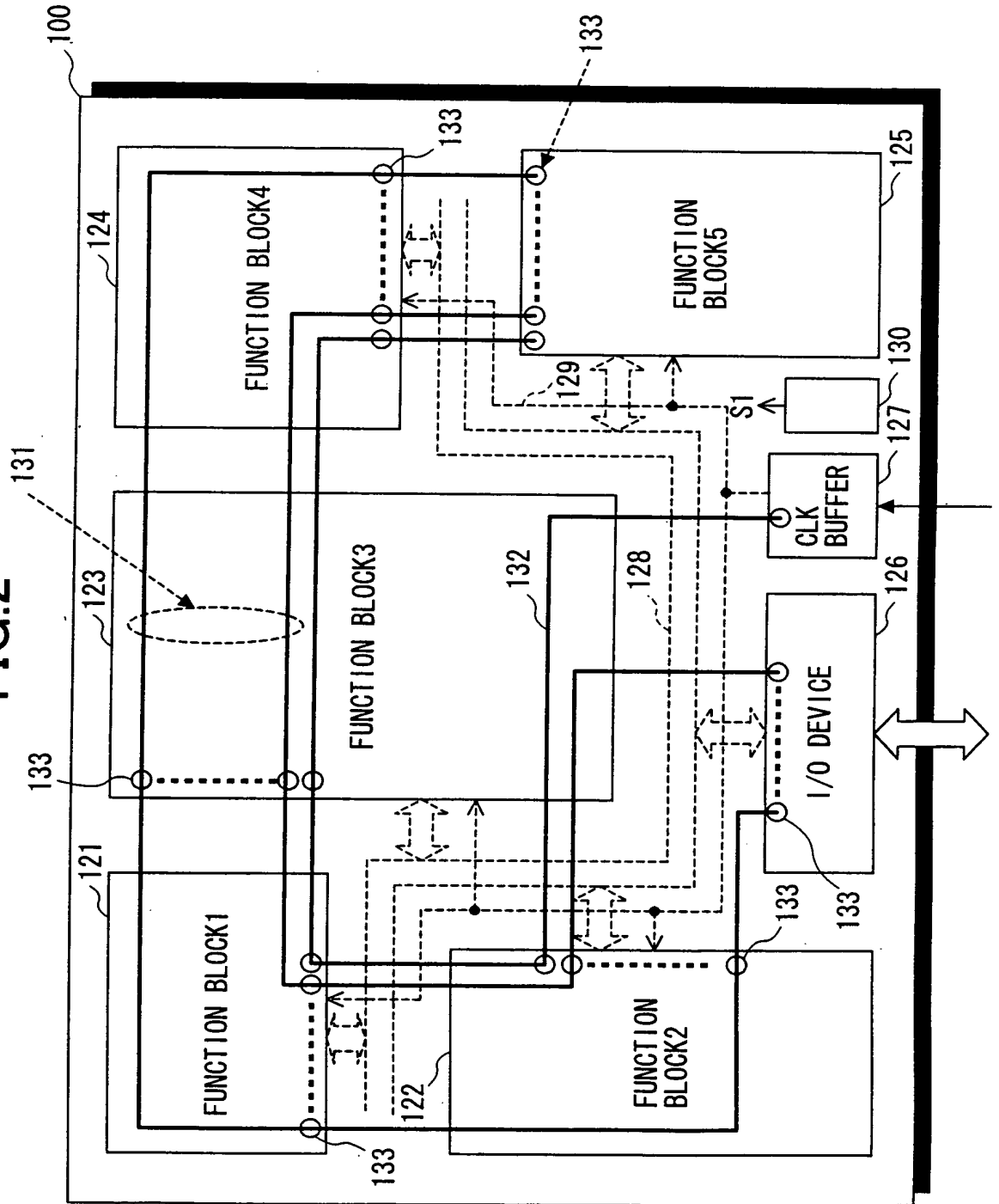


FIG. 3

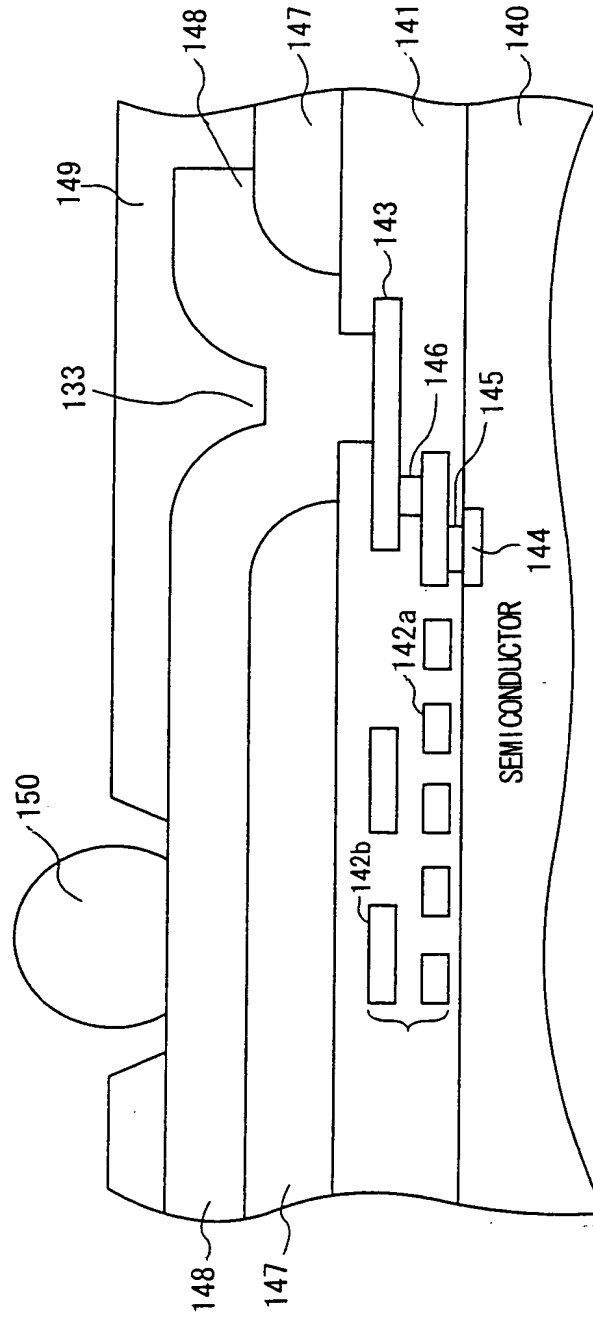


FIG.4

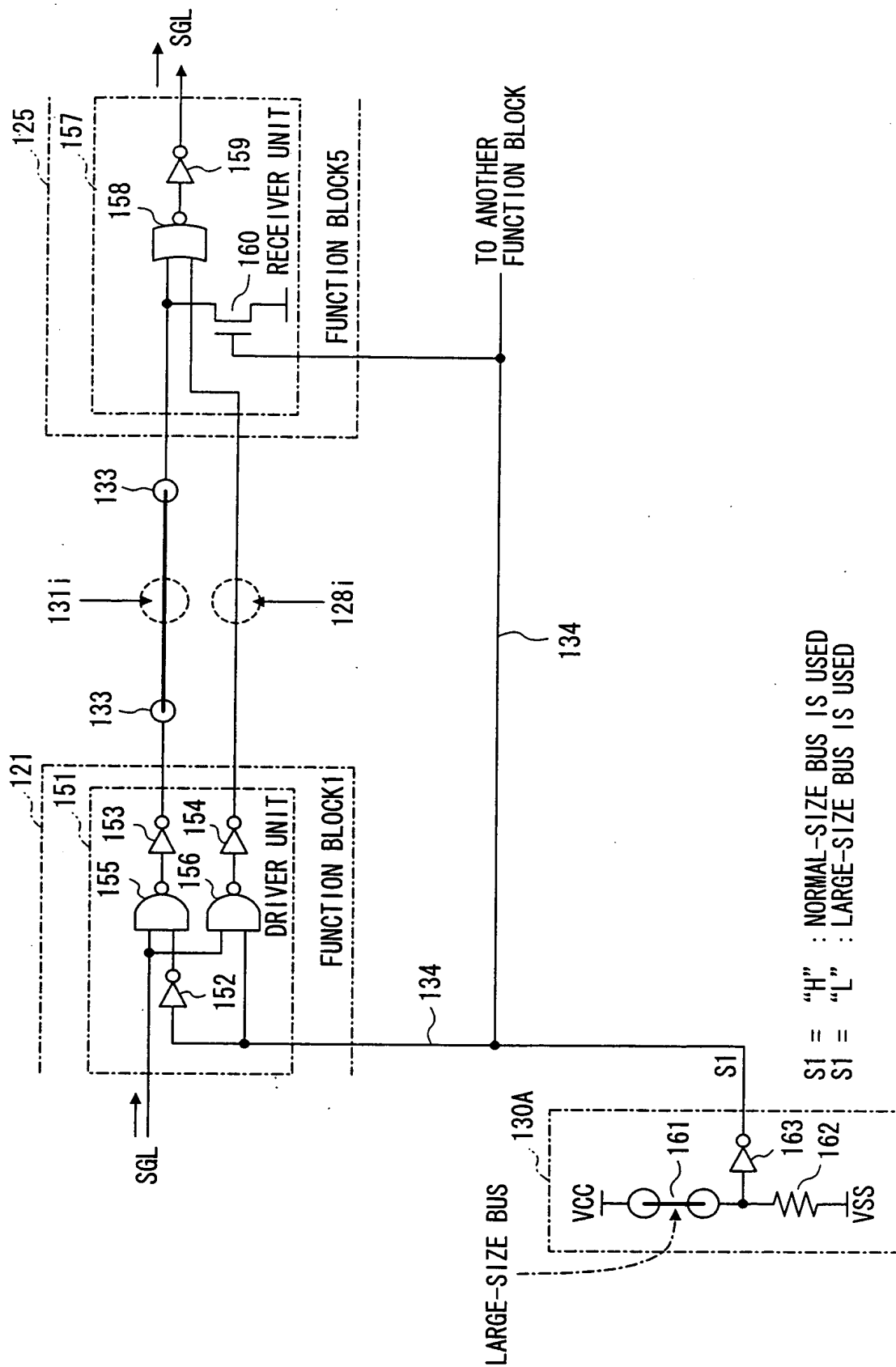


FIG.5

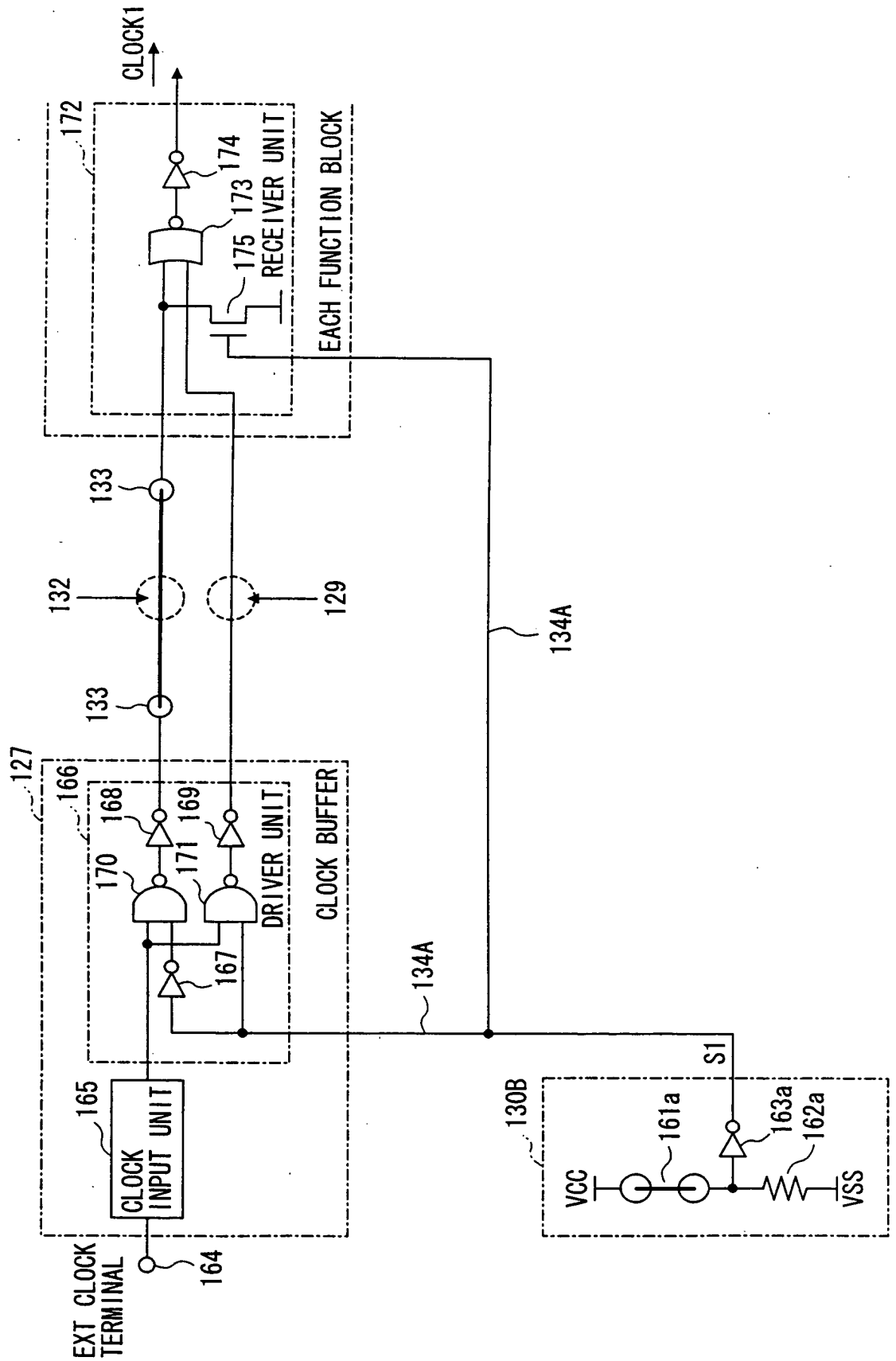


FIG.6

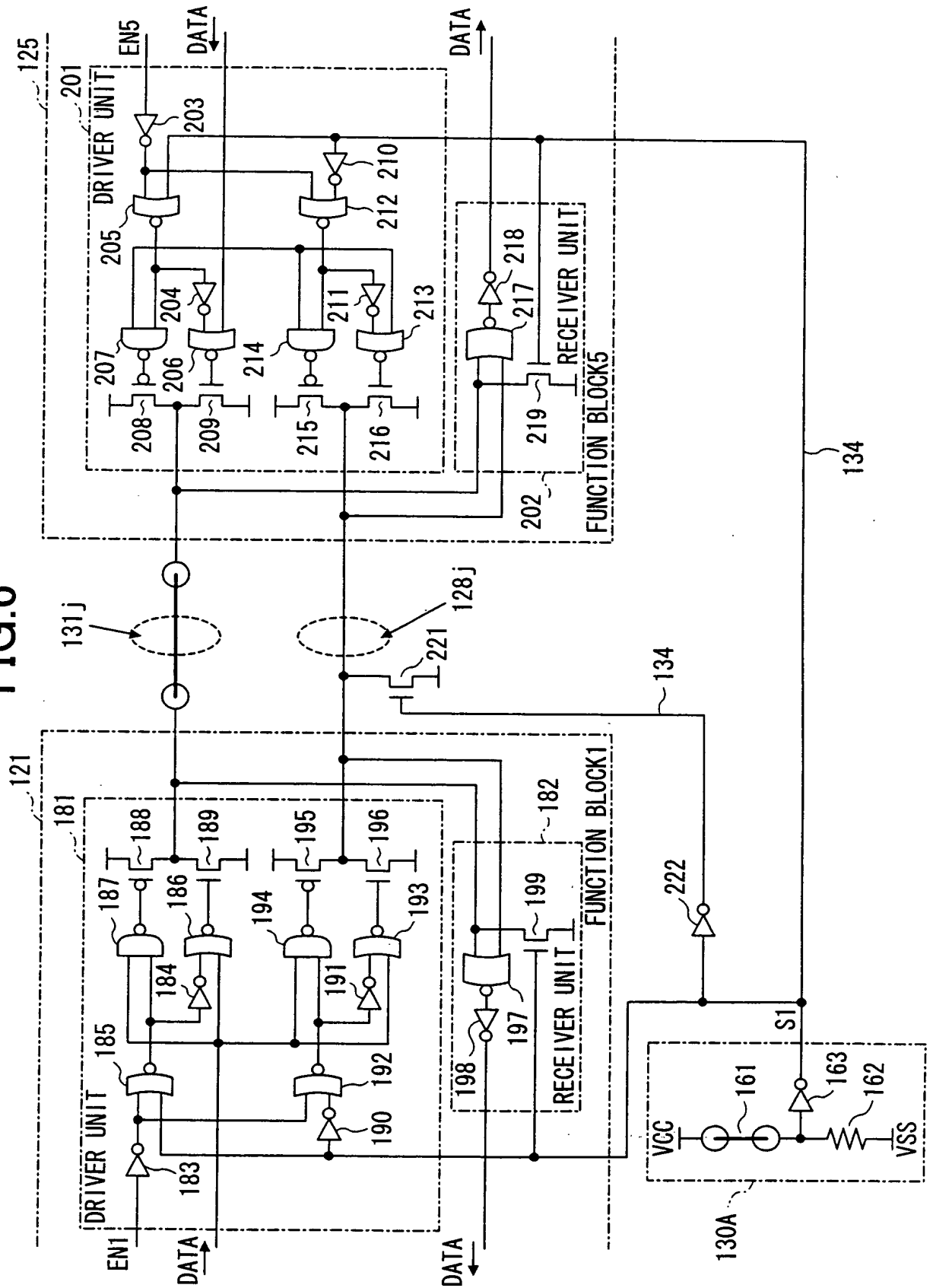


FIG.7A

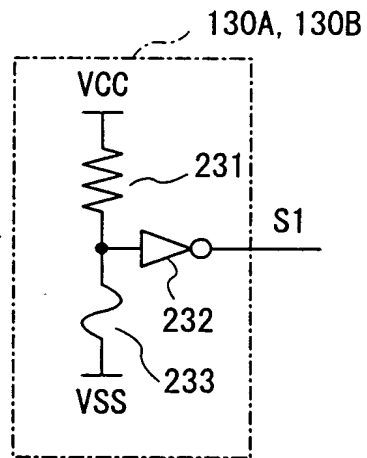


FIG.7B

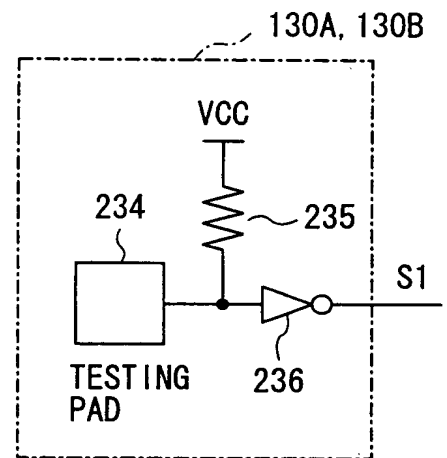


FIG.7C

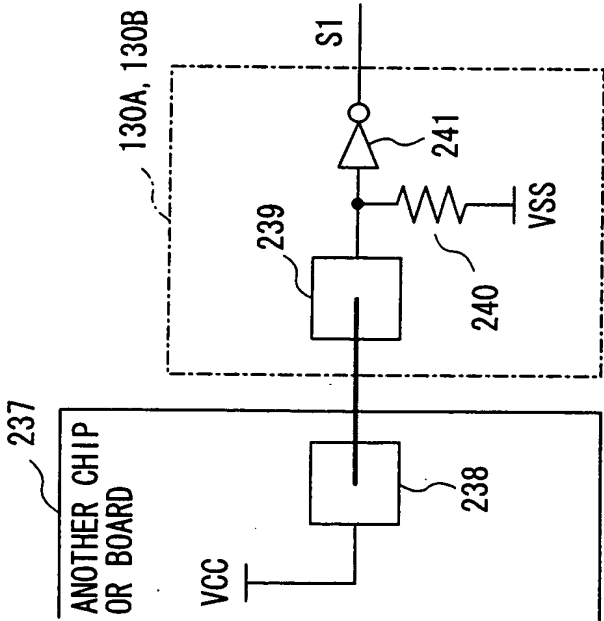


FIG.7D

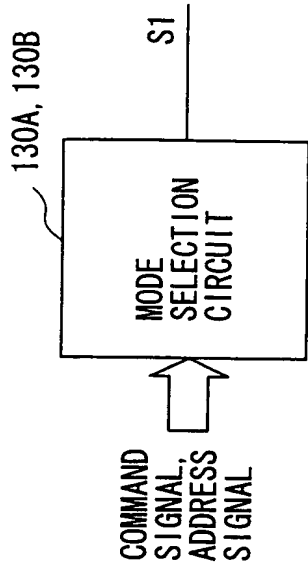


FIG.8

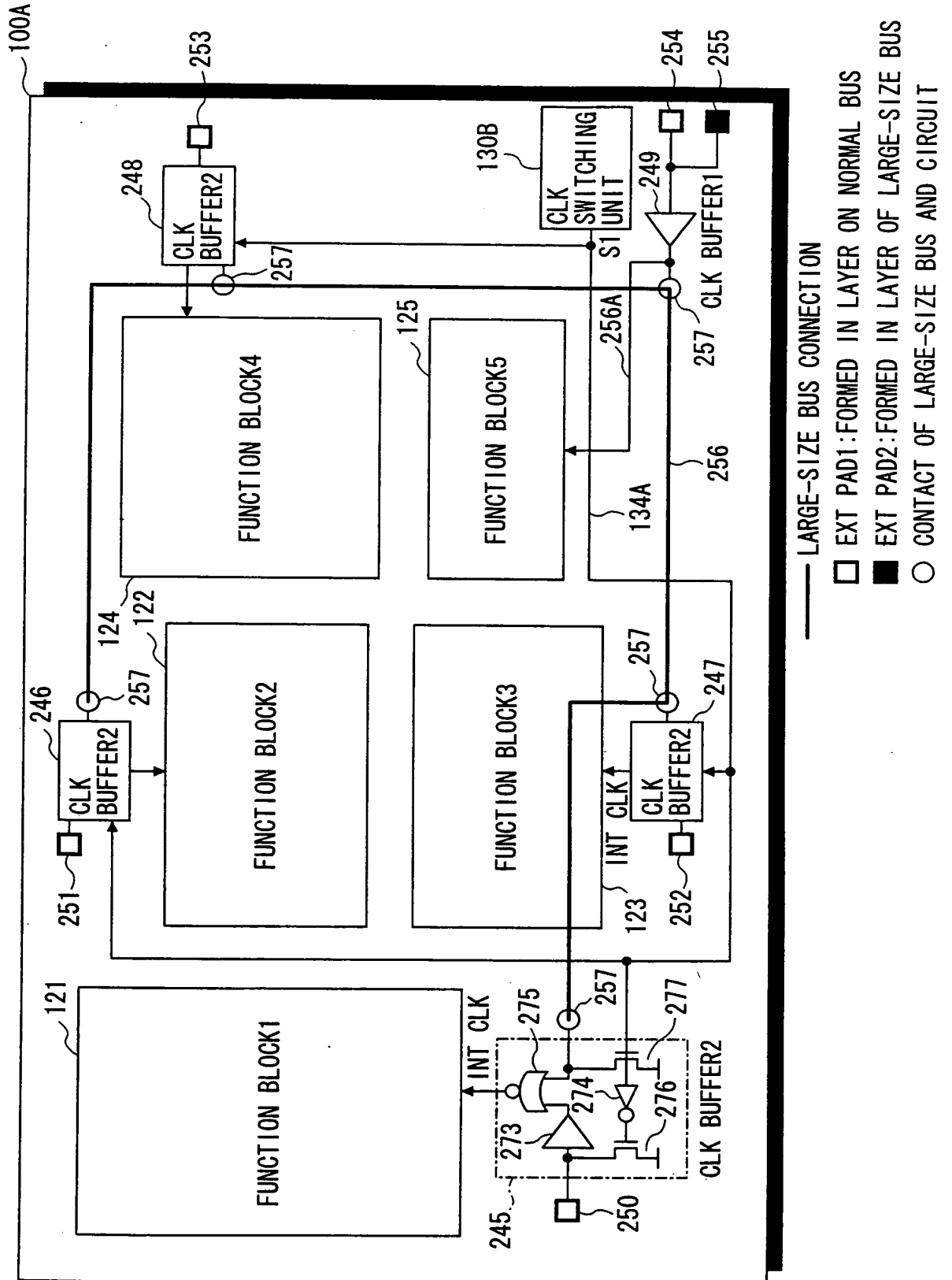
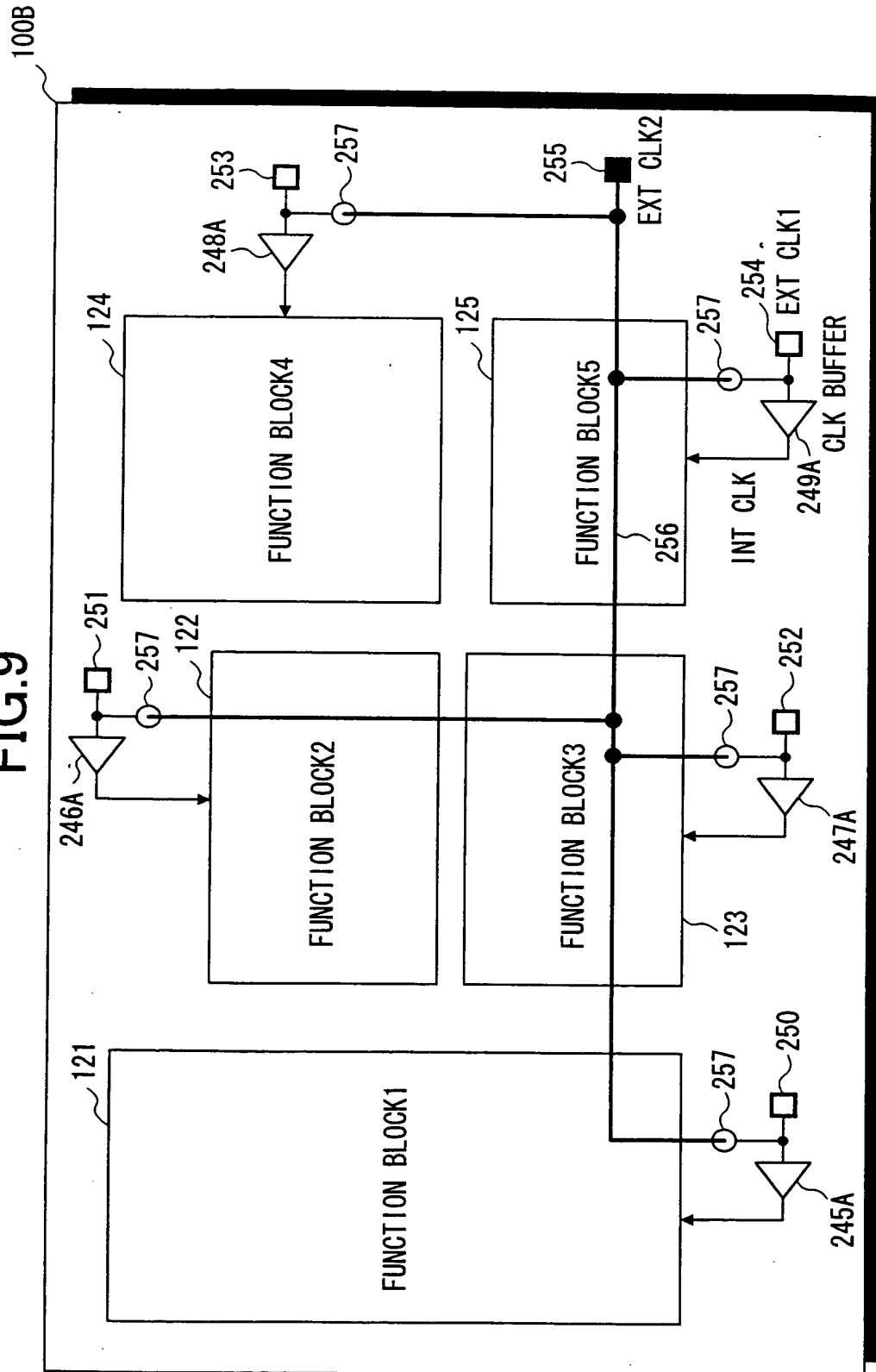


FIG.9



- LARGE-SIZE BUS CONNECTION
- EXT PAD1: FORMED IN LAYER ON NORMAL BUS
 - EXT PAD2: FORMED IN LAYER OF LARGE-SIZE BUS
 - CONTACT OF LARGE-SIZE BUS AND CIRCUIT

FIG. 10

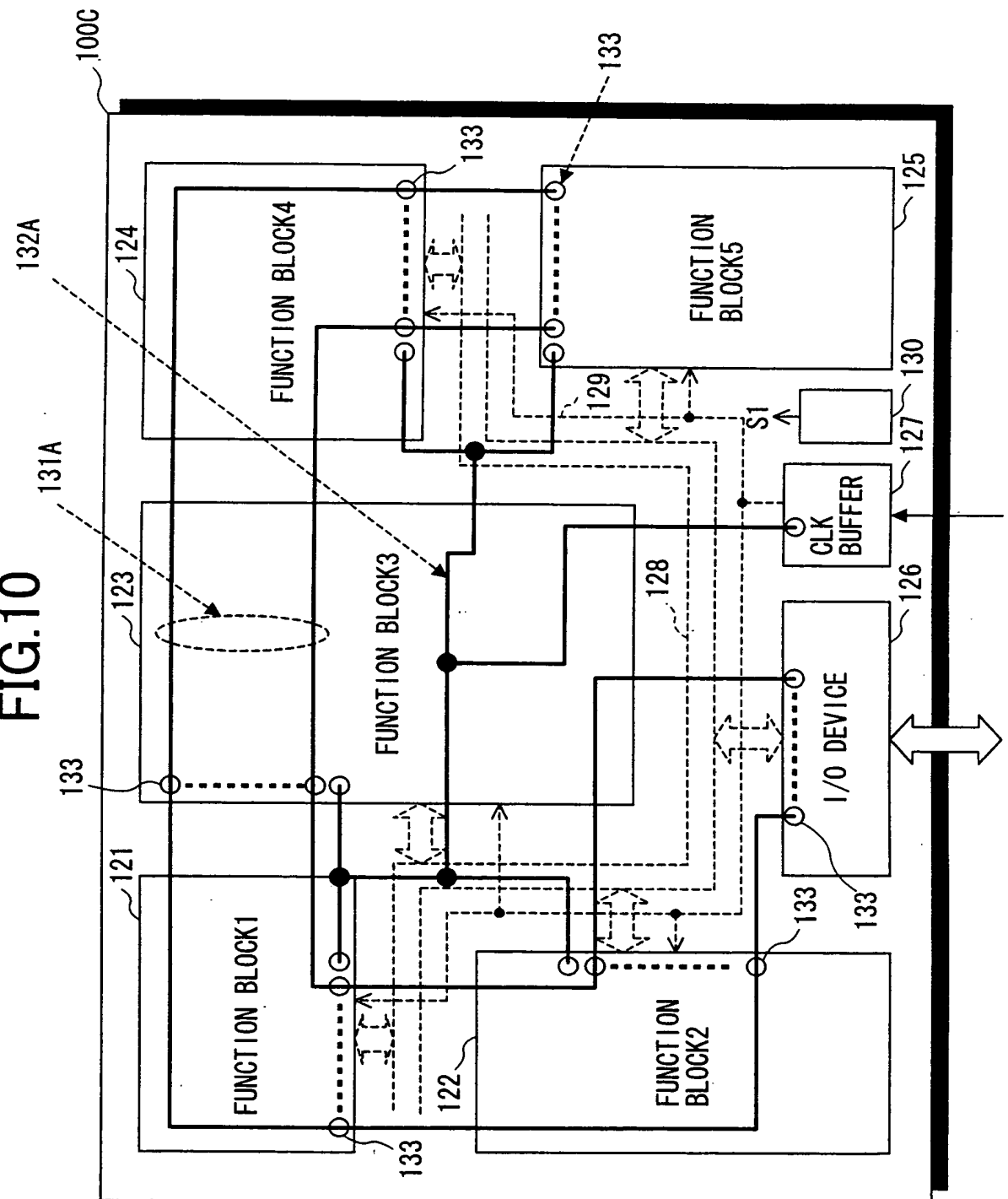
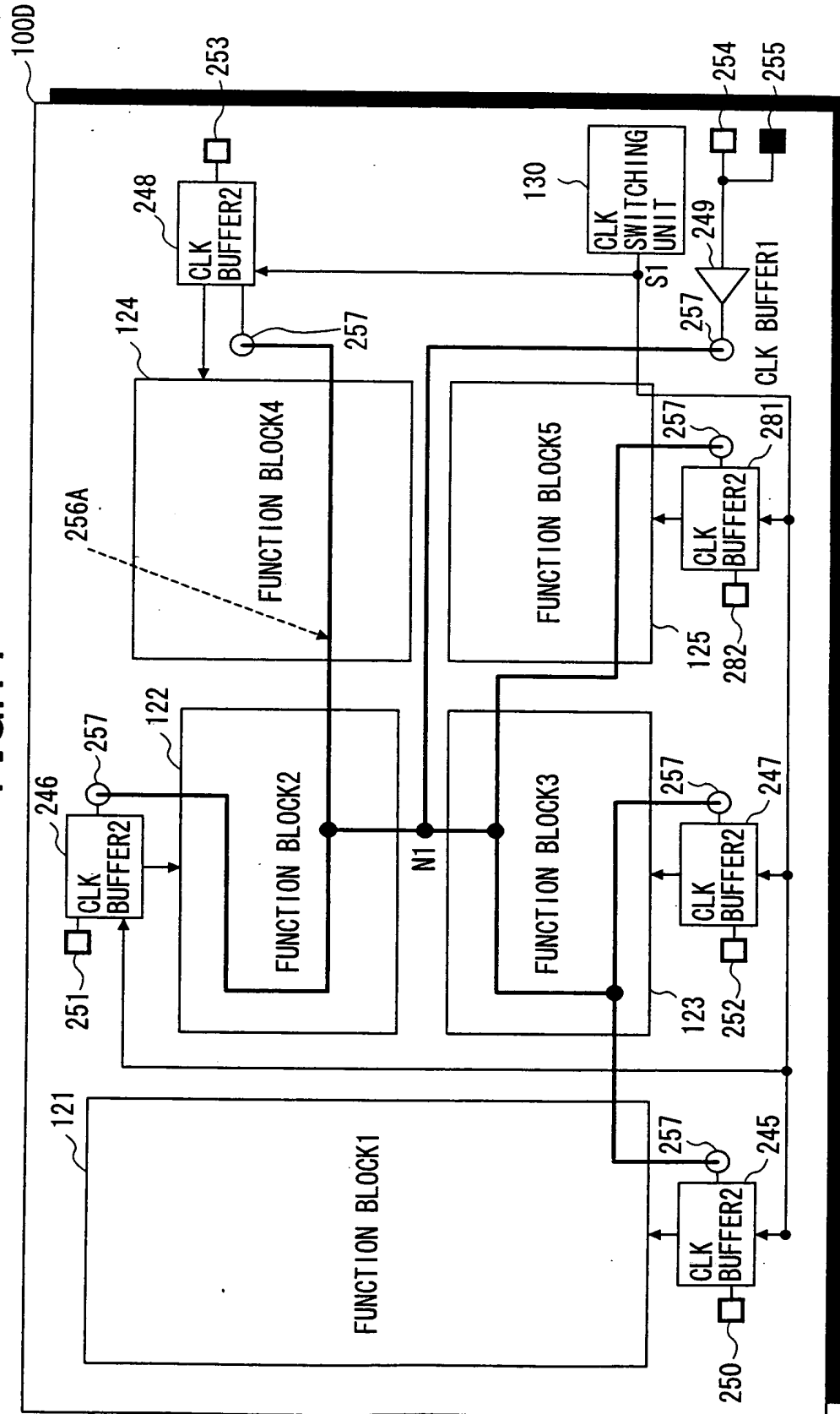


FIG.11



- LARGE-SIZE BUS CONNECTION
- EXT PAD1: FORMED IN LAYER ON NORMAL BUS
 - EXT PAD2: FORMED IN LAYER OF LARGE-SIZE BUS
 - CONTACT OF LARGE-SIZE BUS AND CIRCUIT

FIG.12

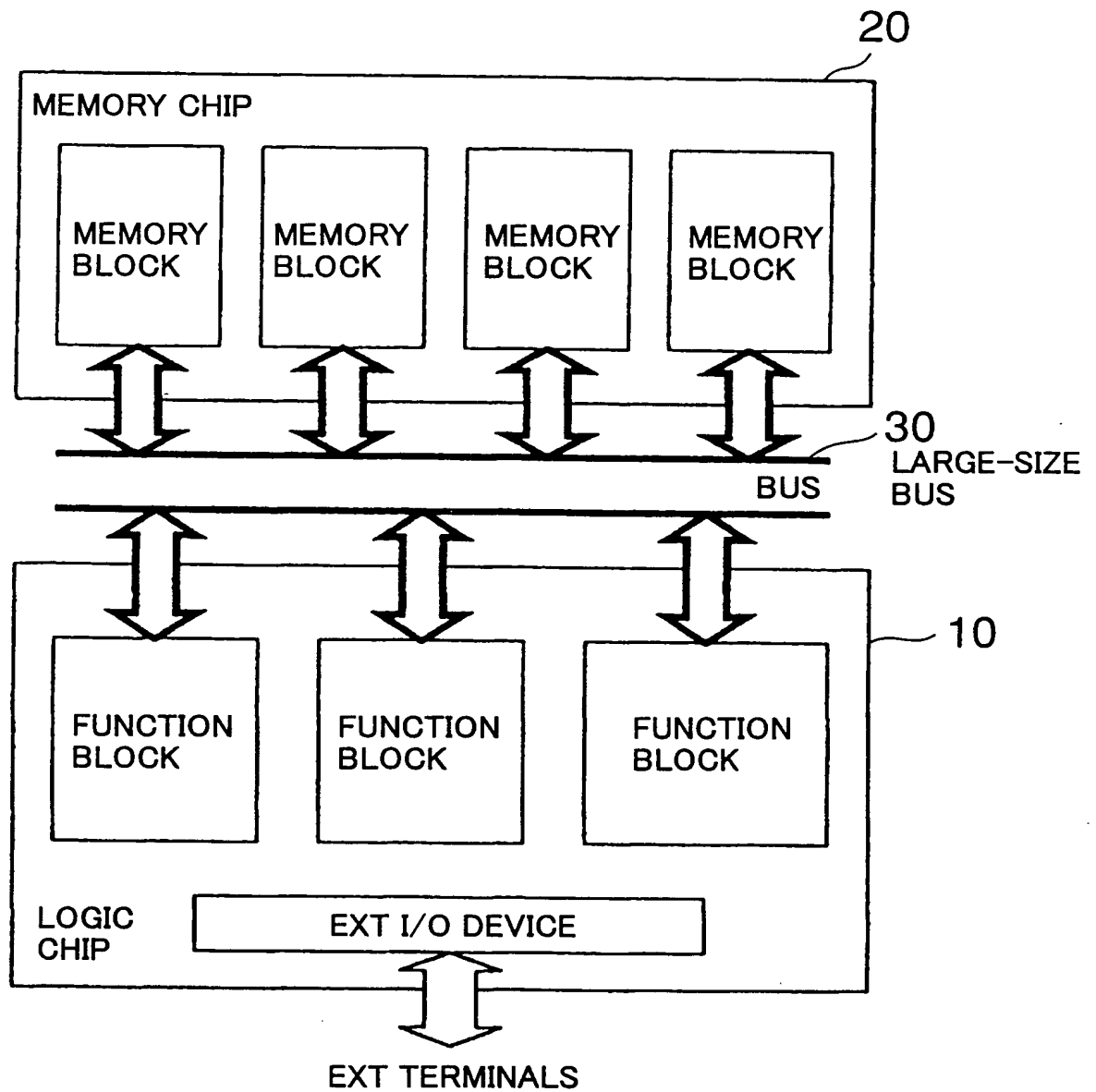


FIG.13

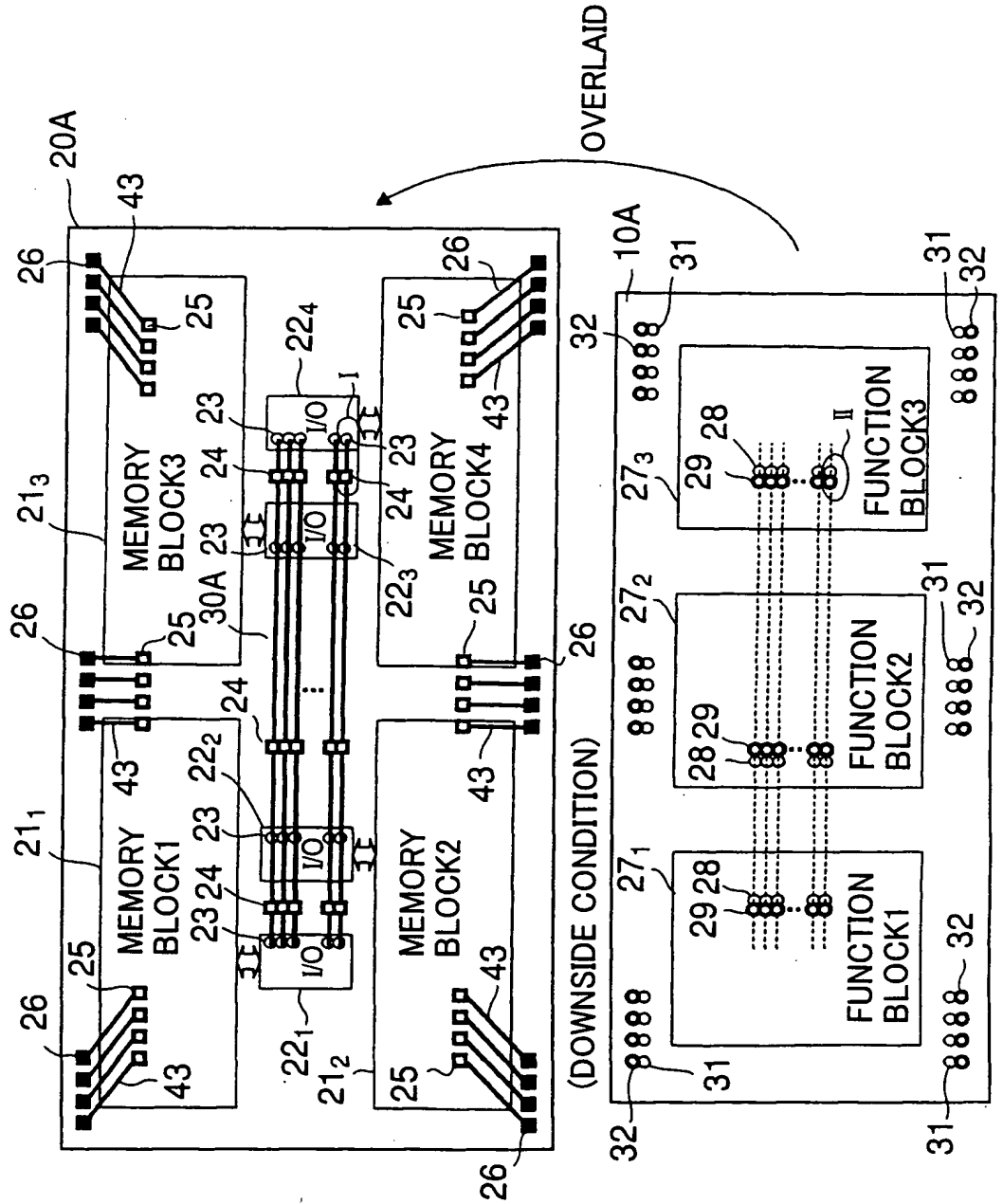


FIG. 14

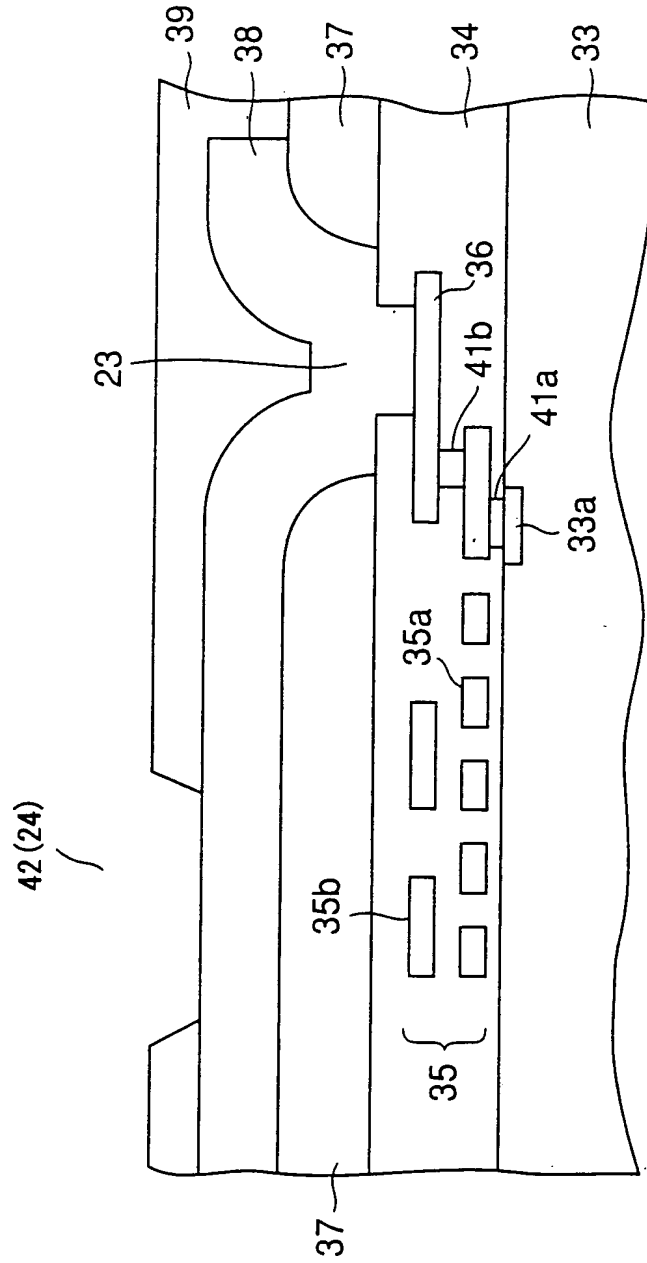


FIG. 15

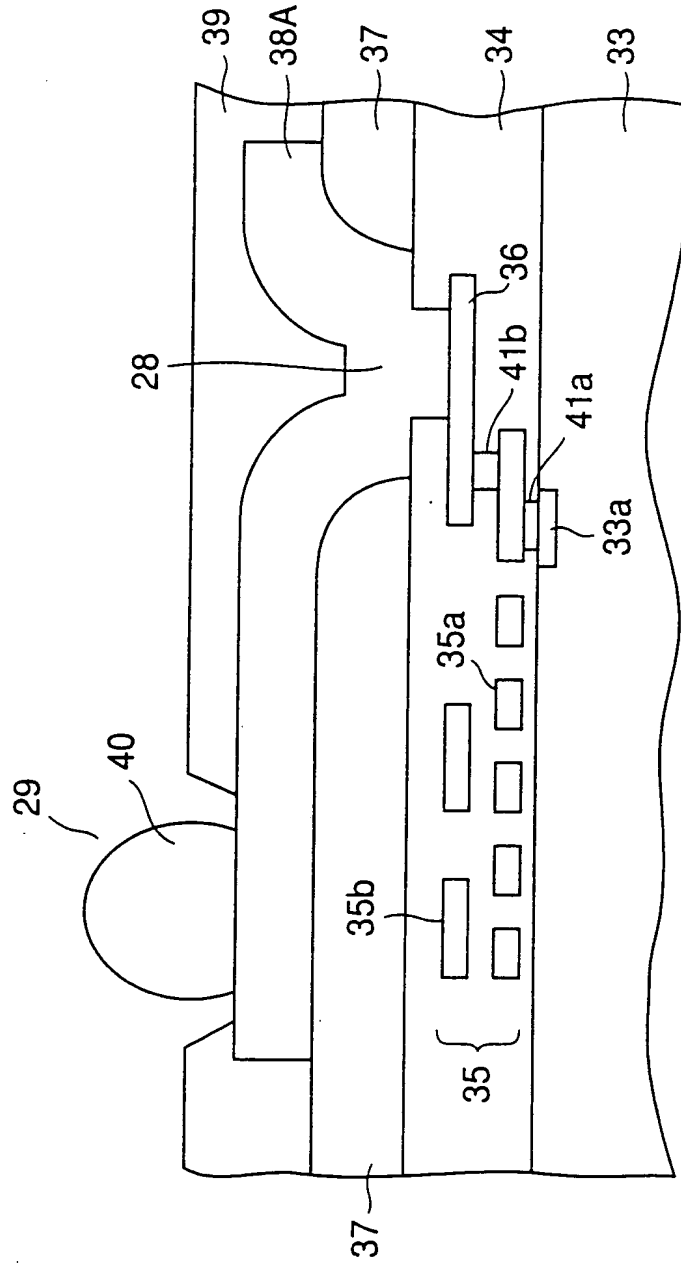
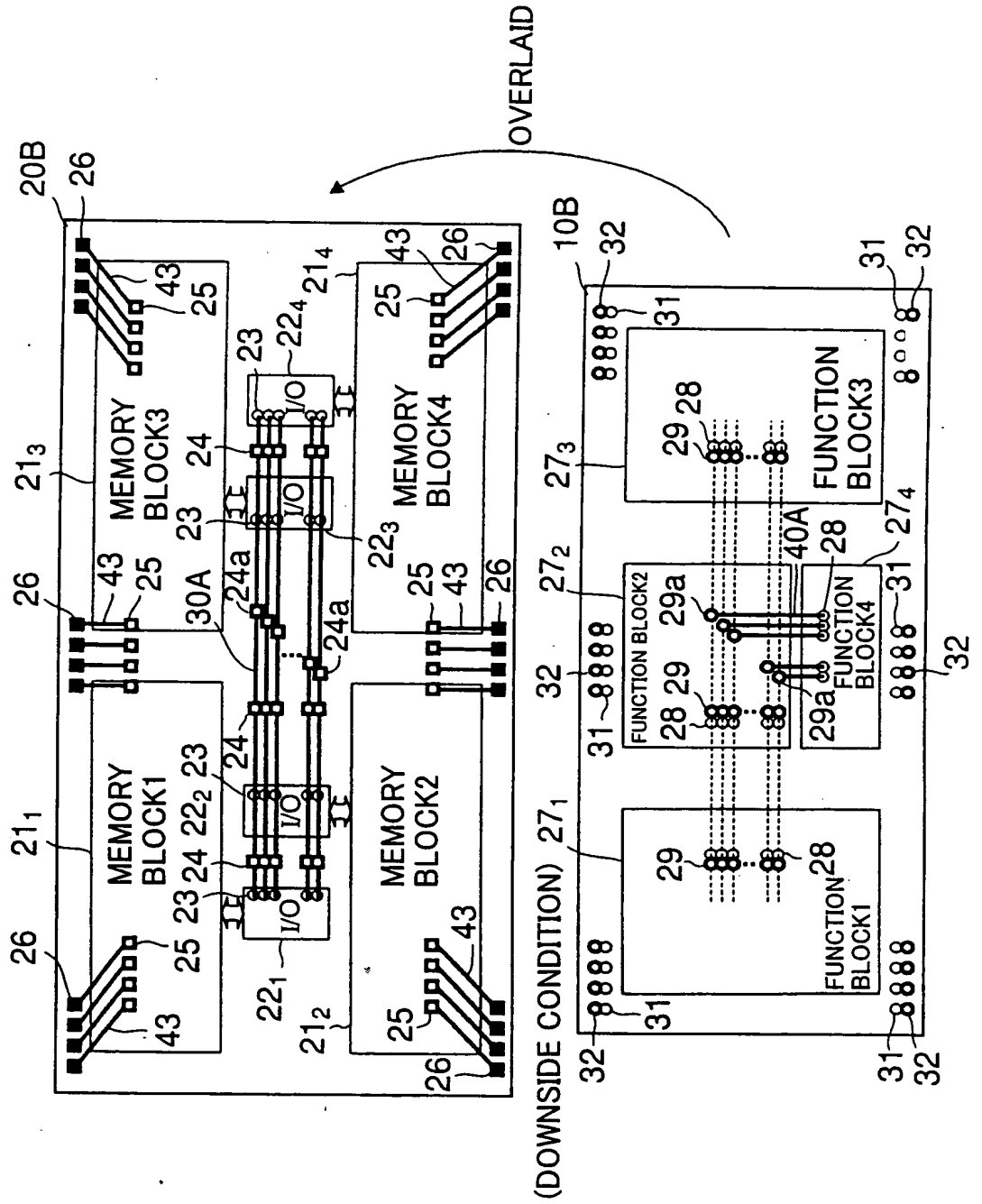


FIG.16



(DOWNSIDE CONDITION)



FIG.18

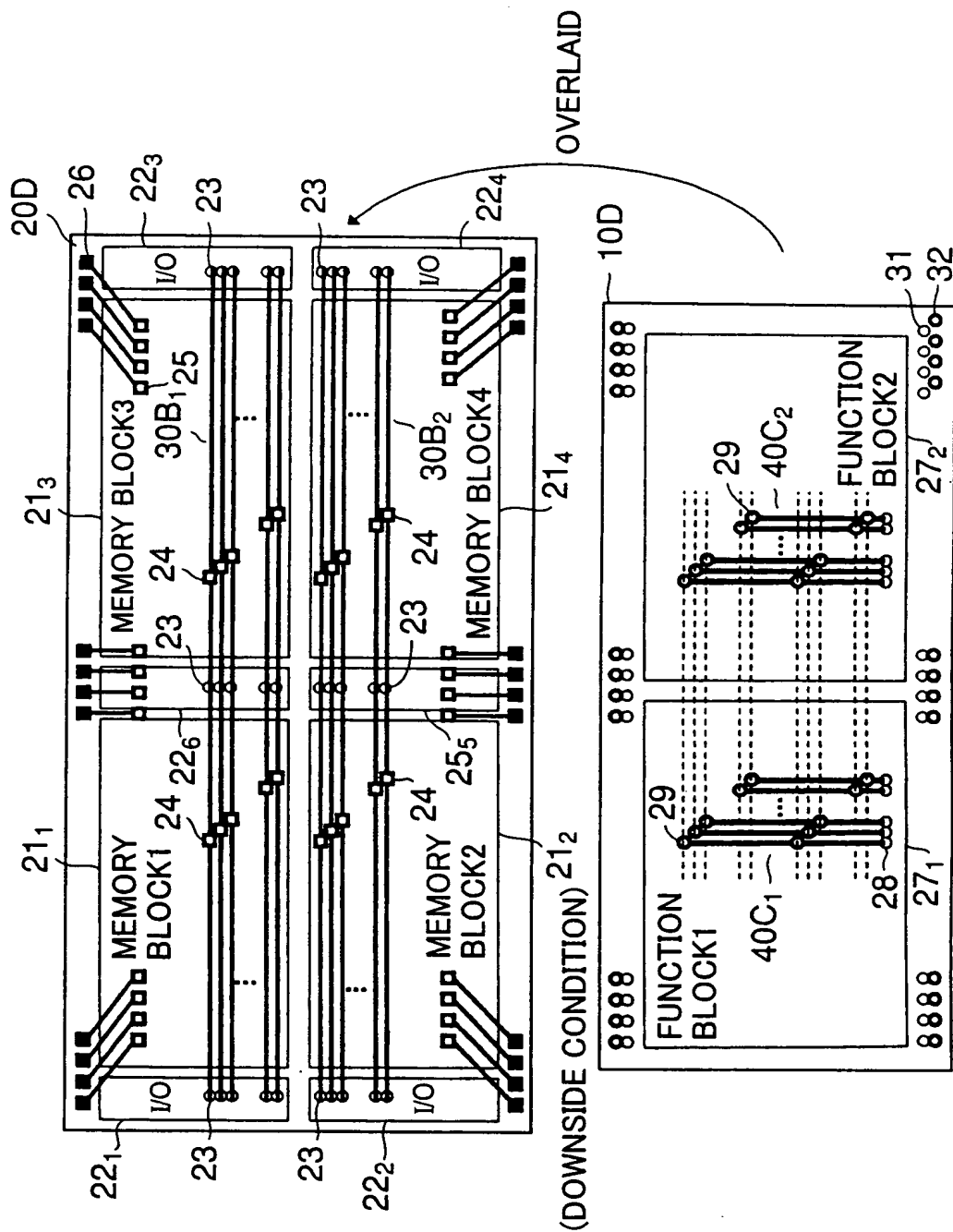


FIG.19

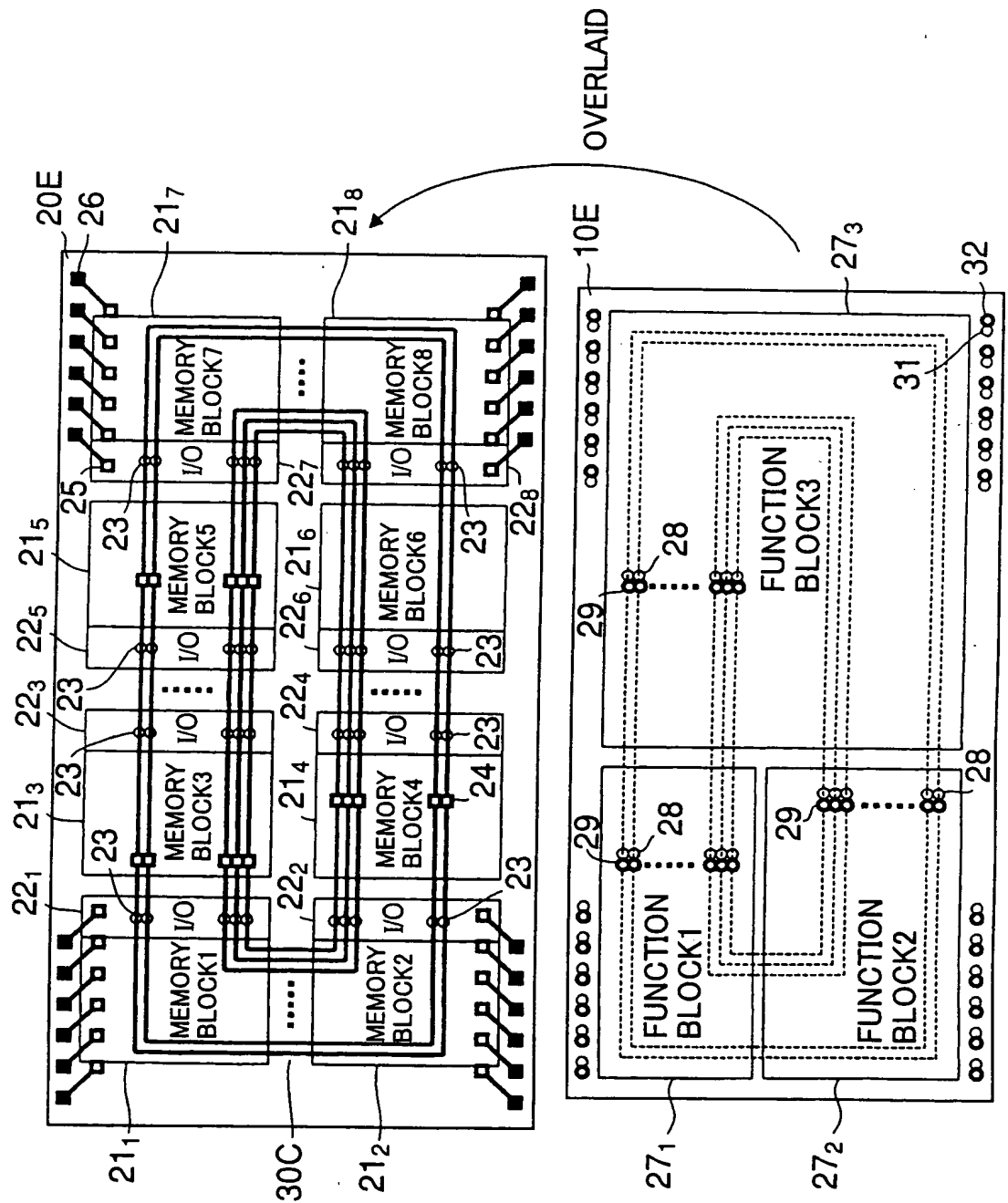


FIG.20

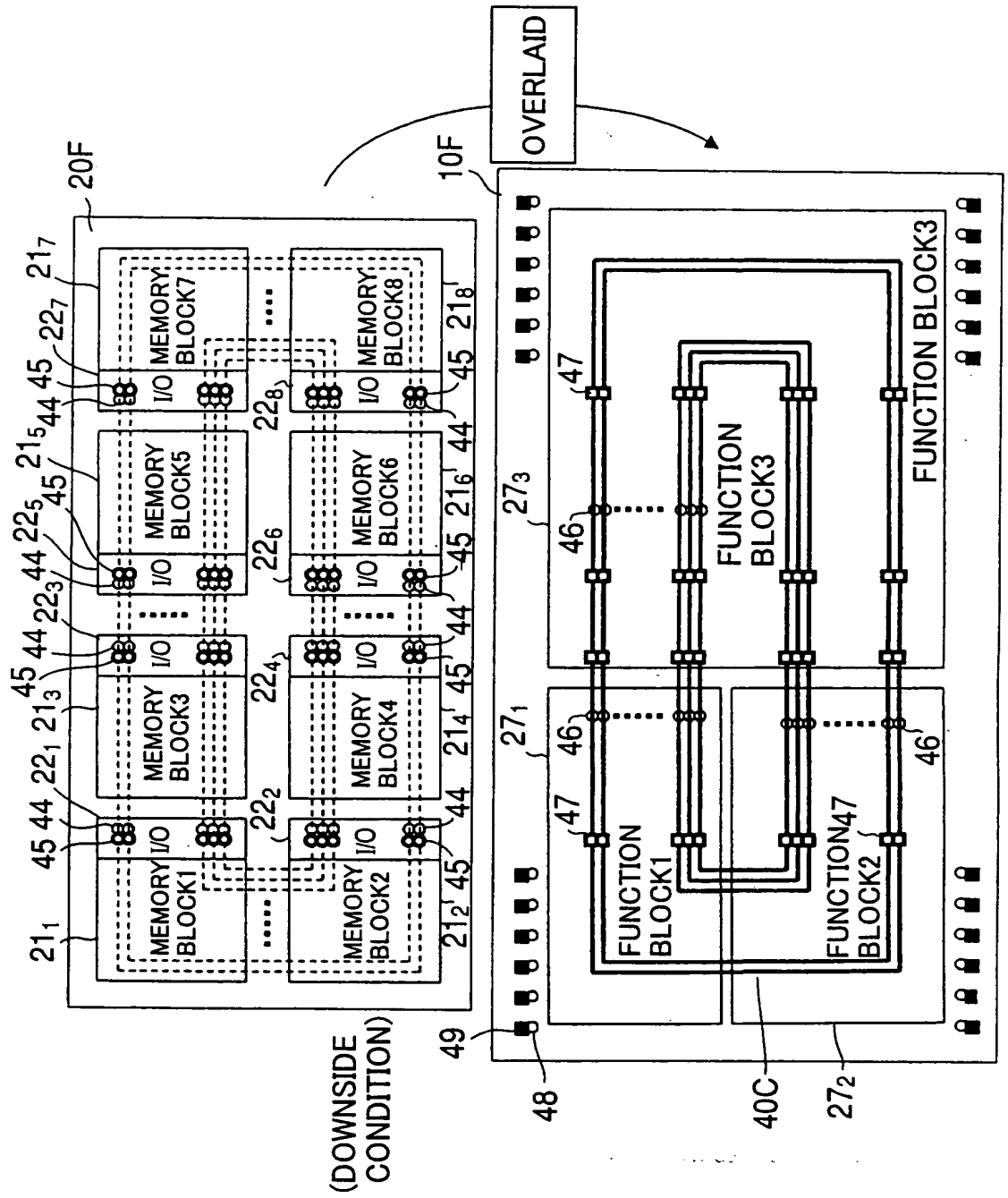


FIG.21

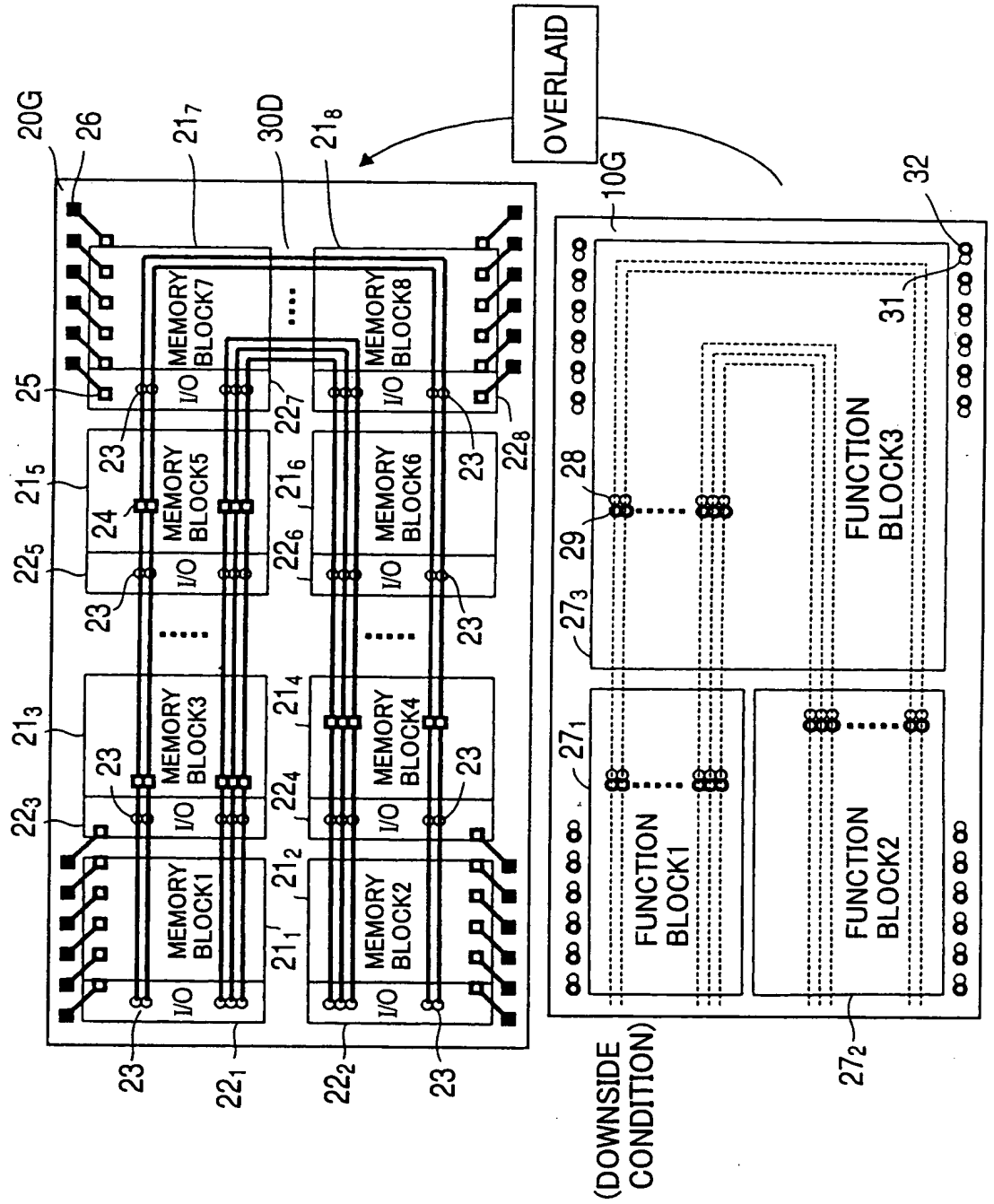


FIG.22

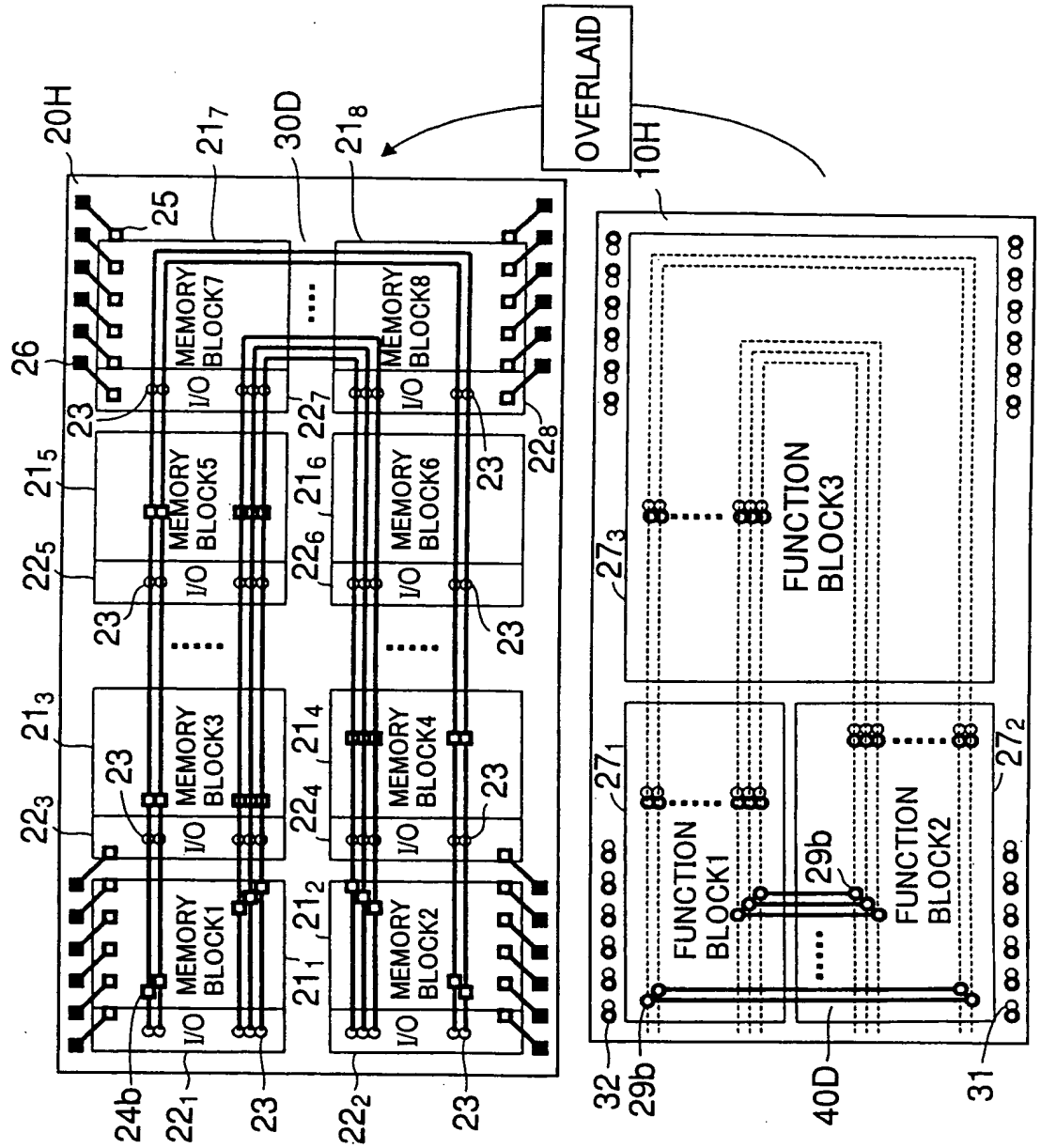


FIG.23

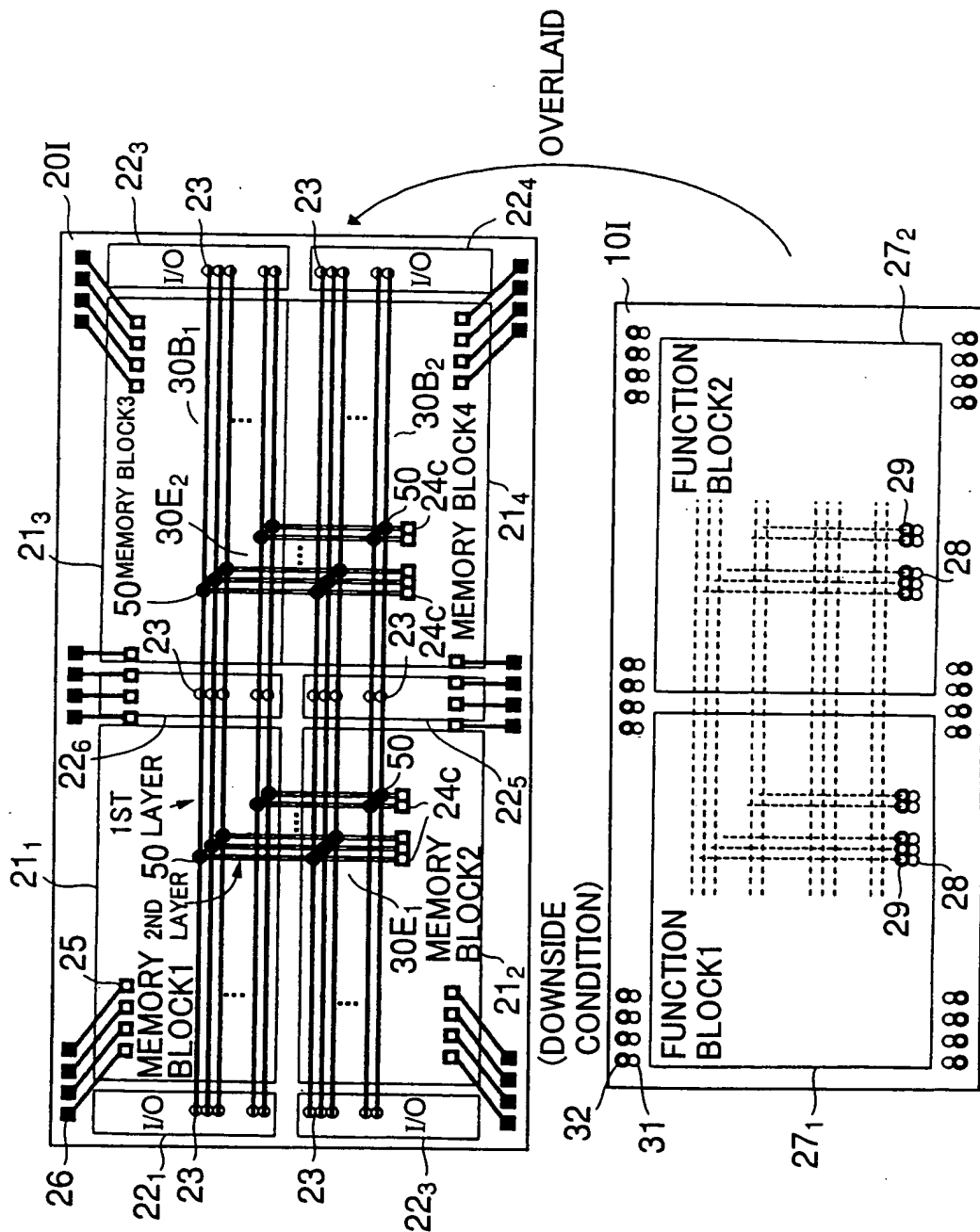


FIG. 24

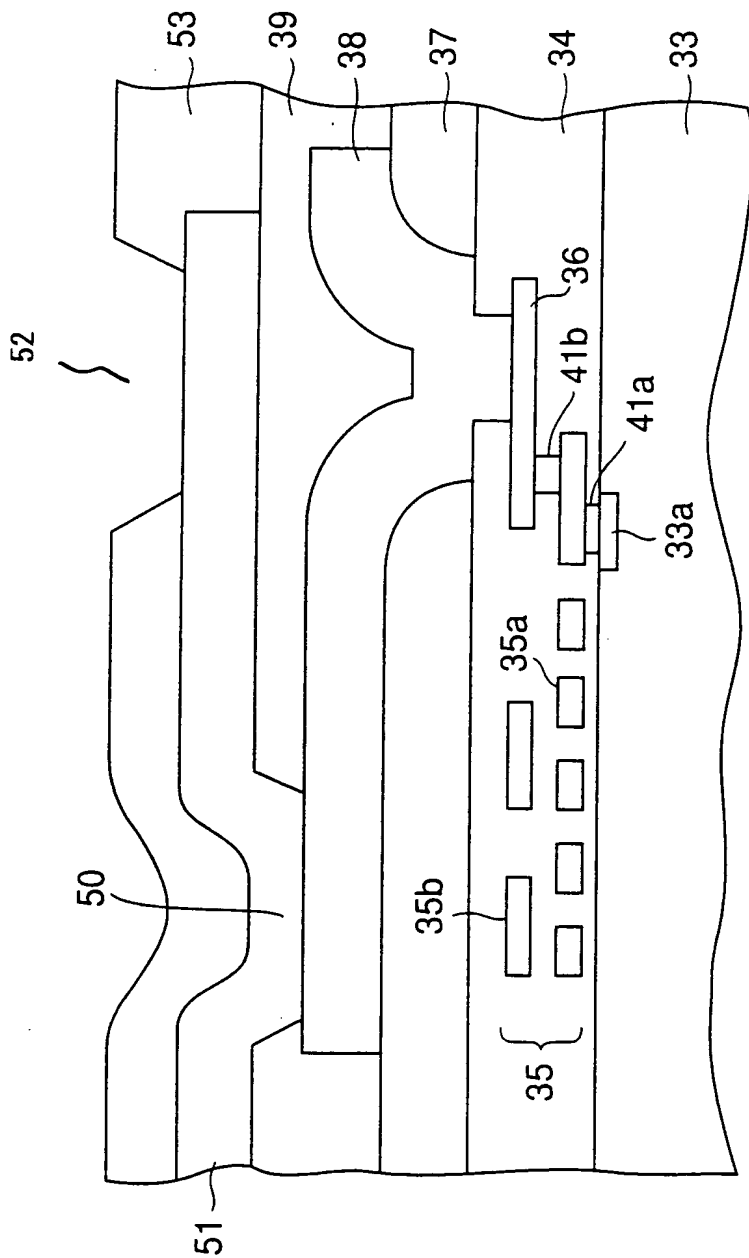


FIG.25

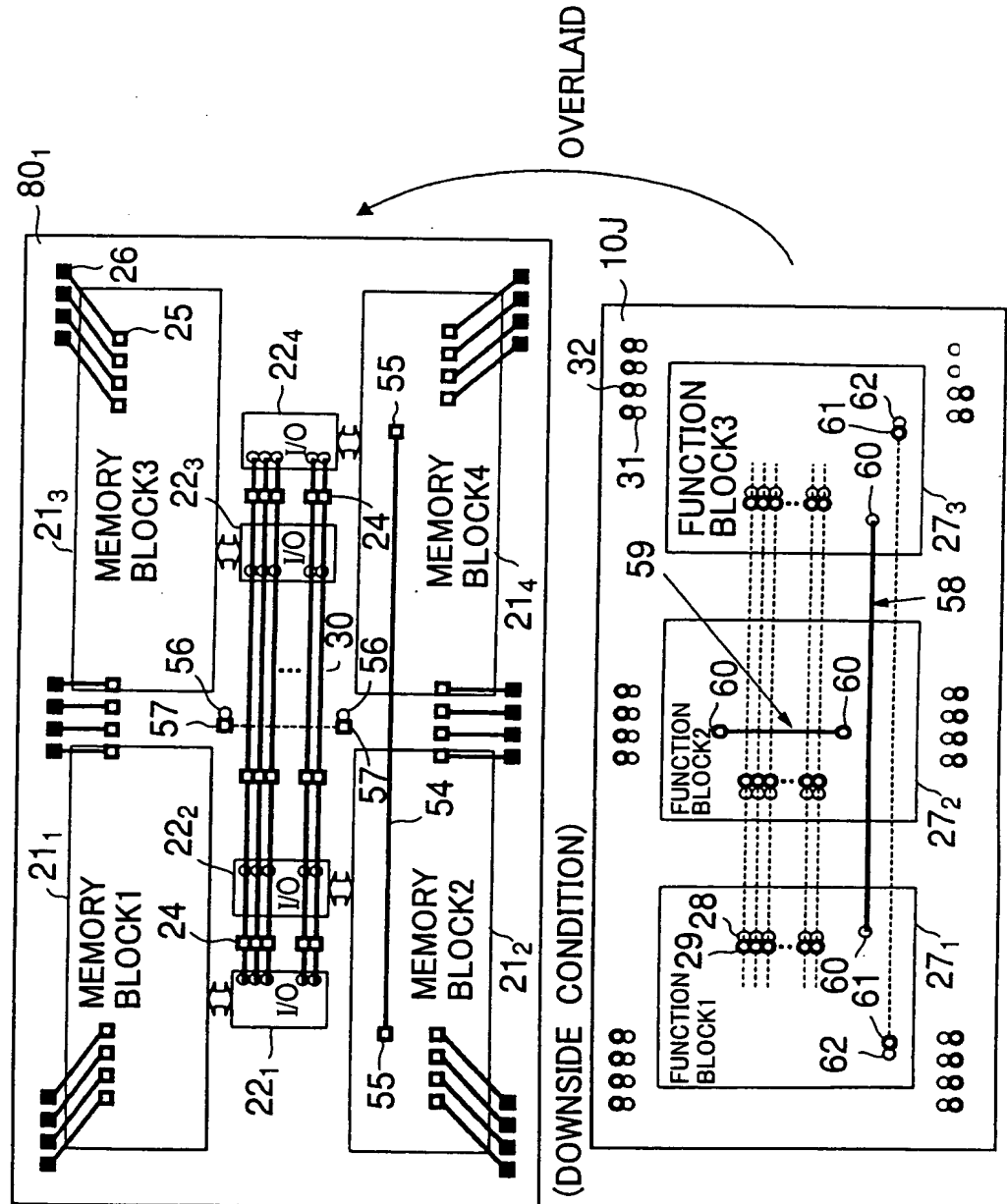


FIG.26

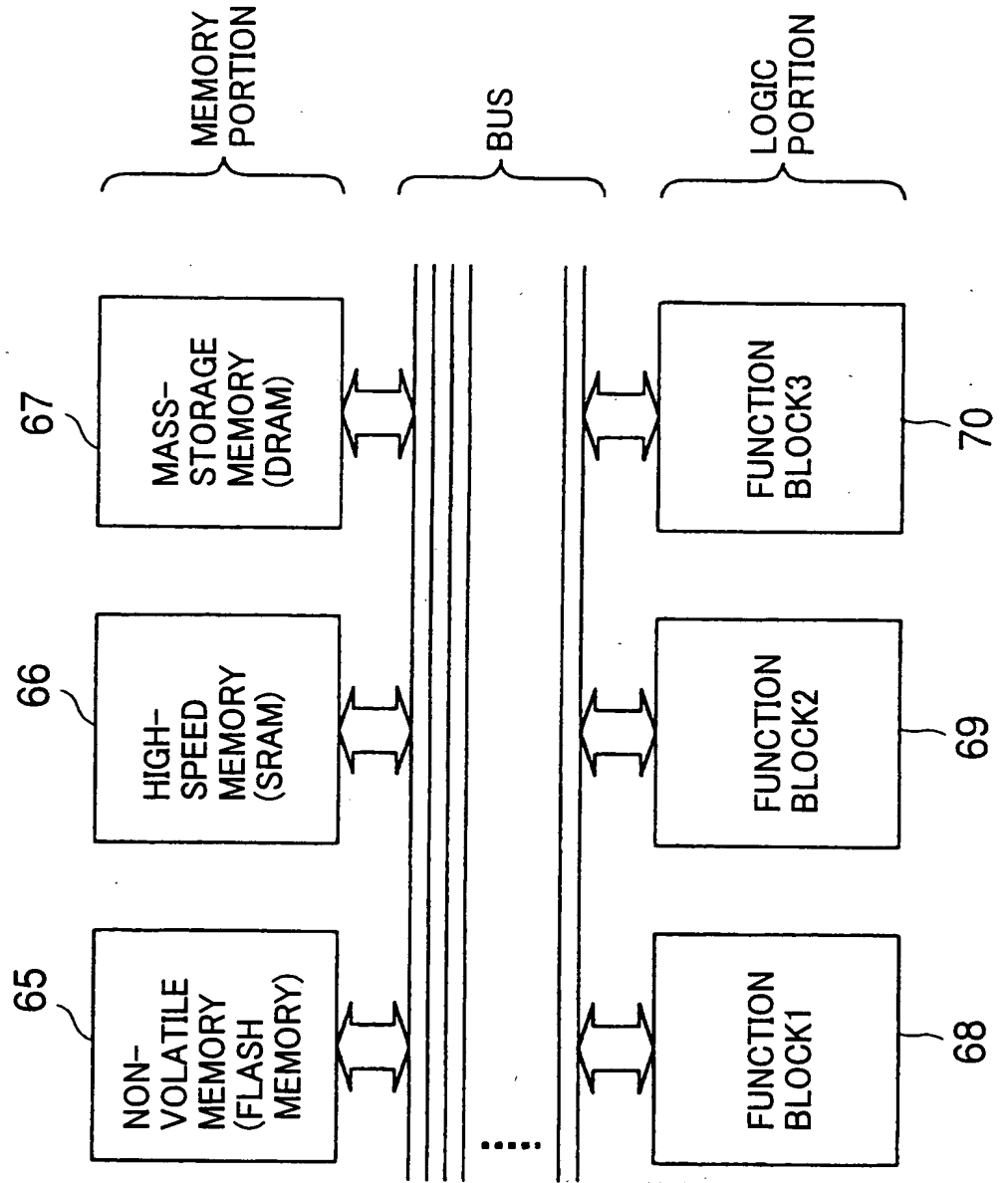


FIG.27

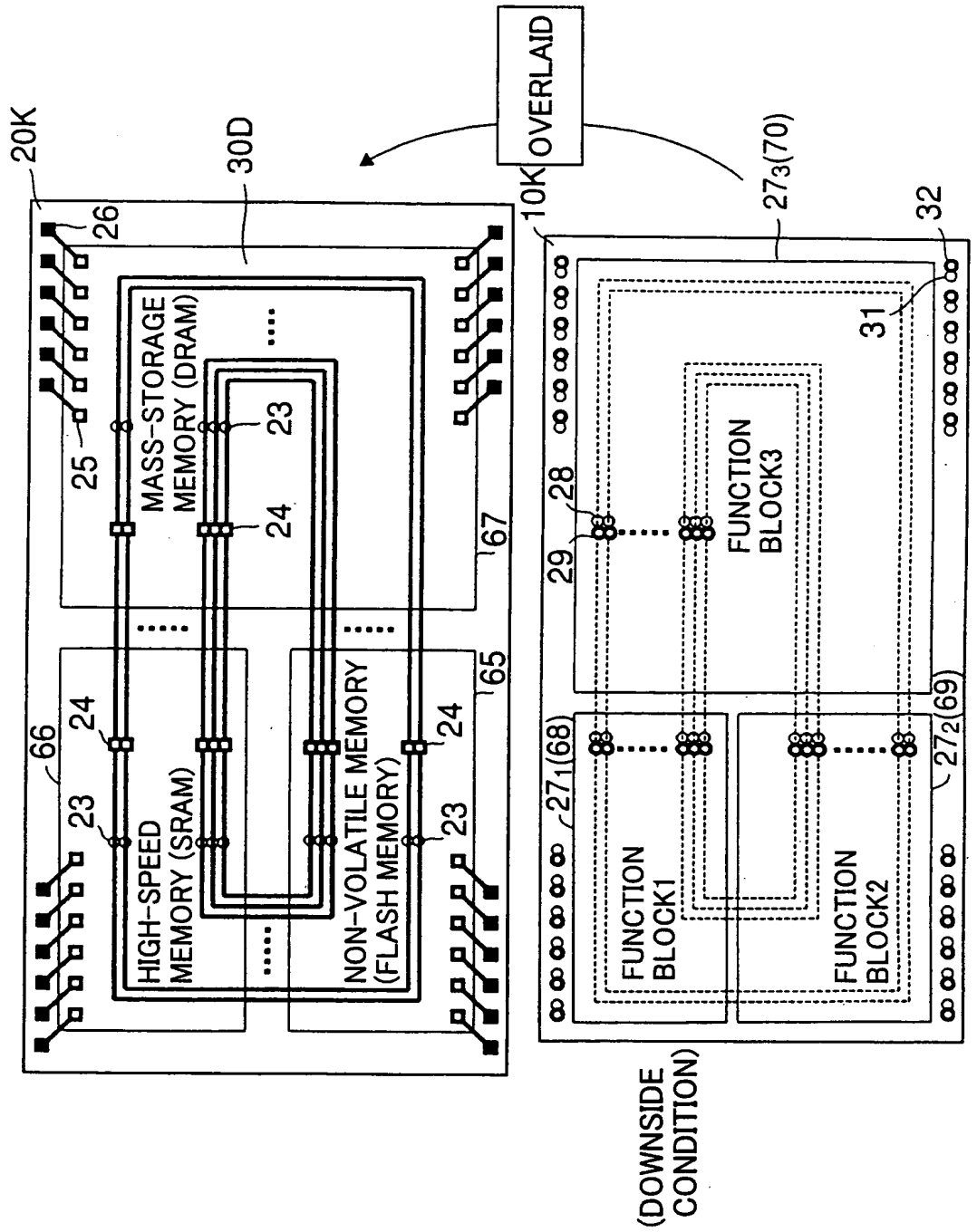


FIG.28

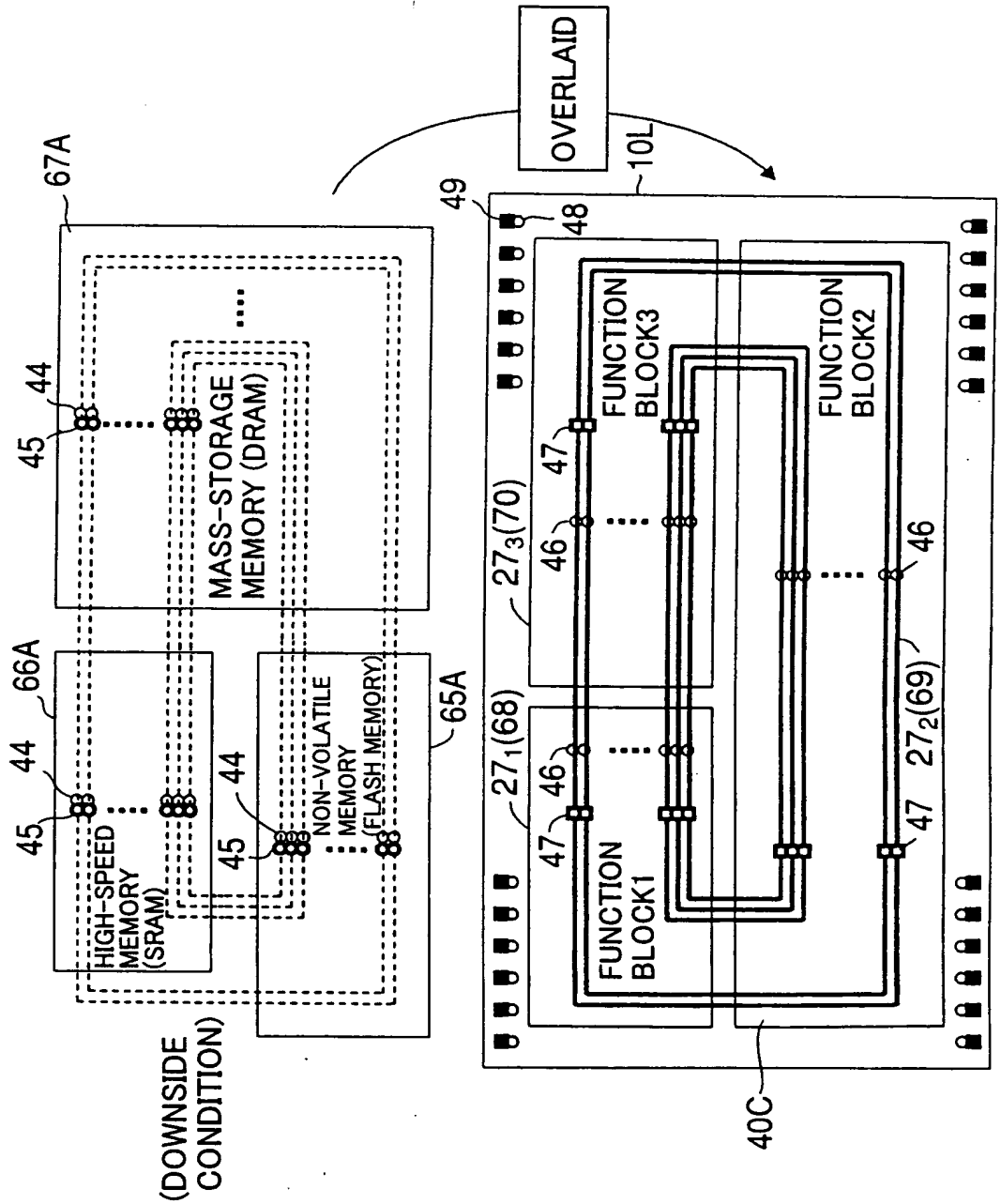


FIG.29

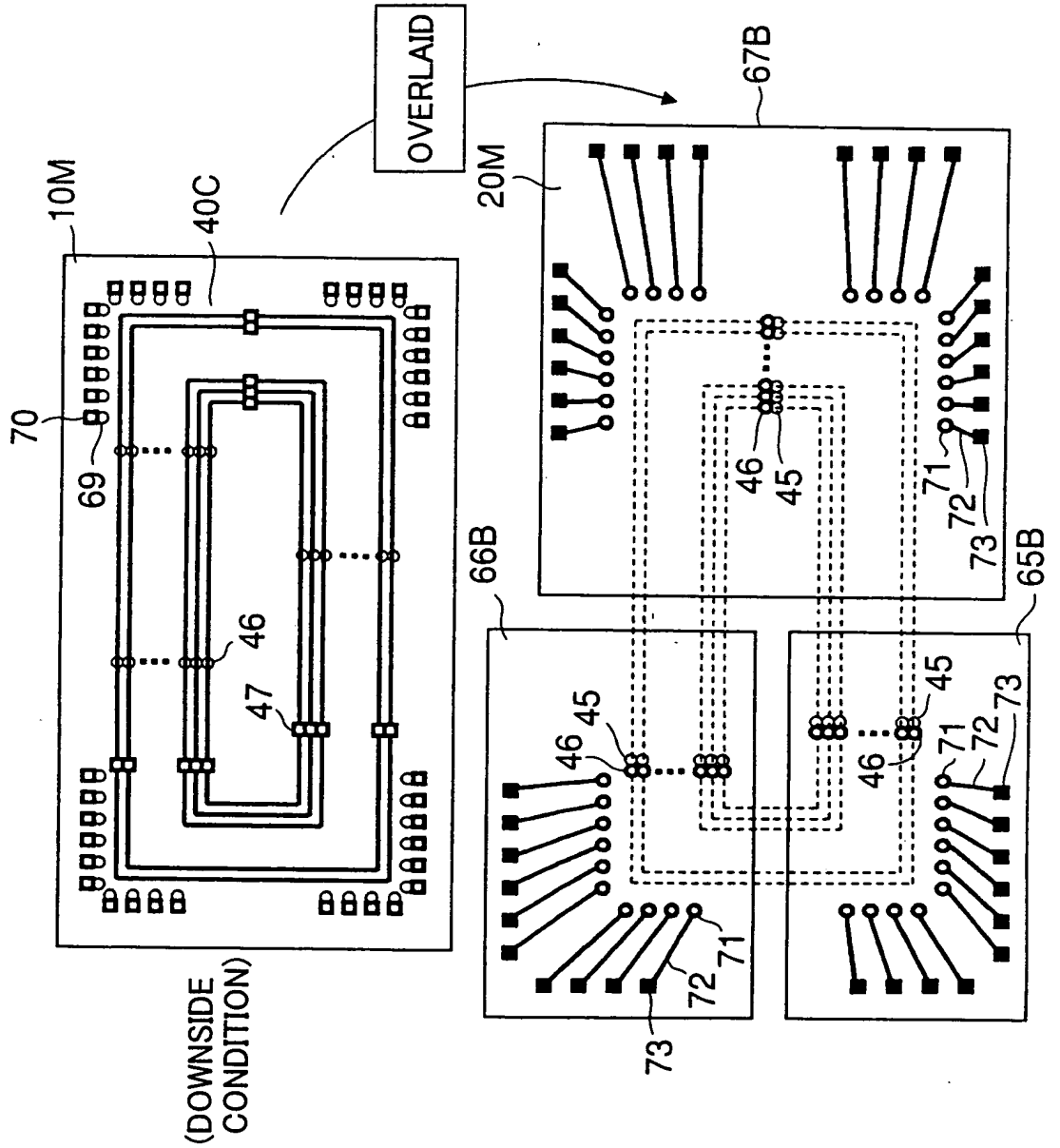


FIG. 30

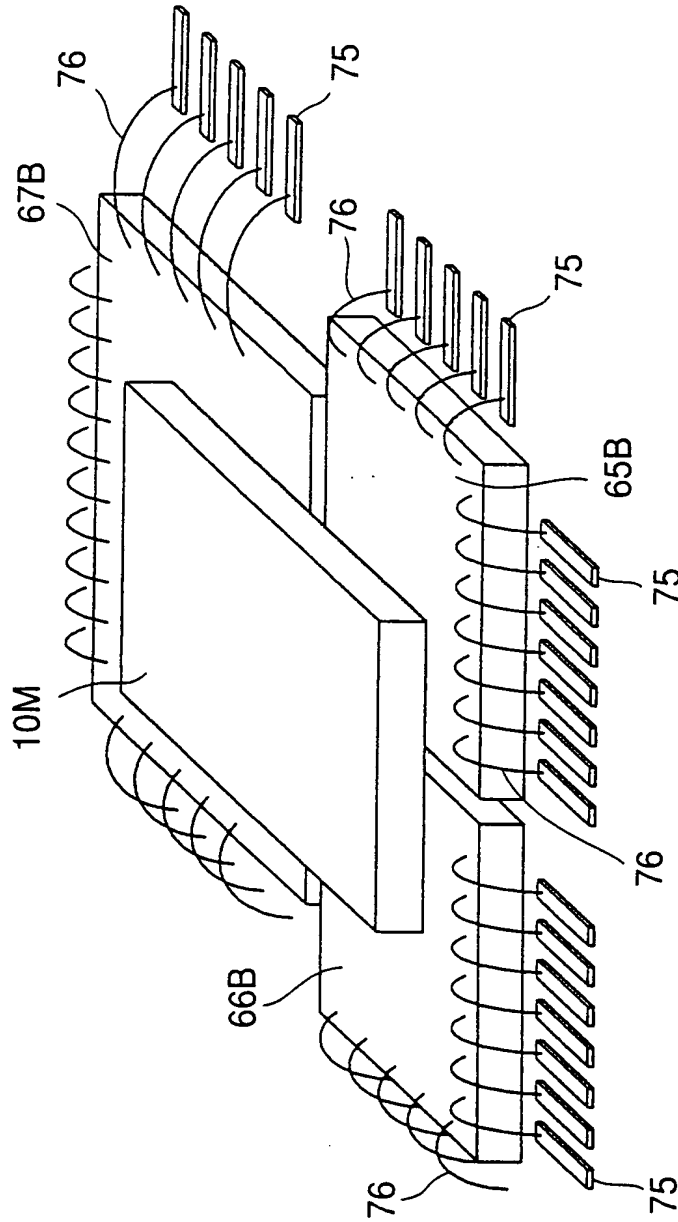


FIG. 31

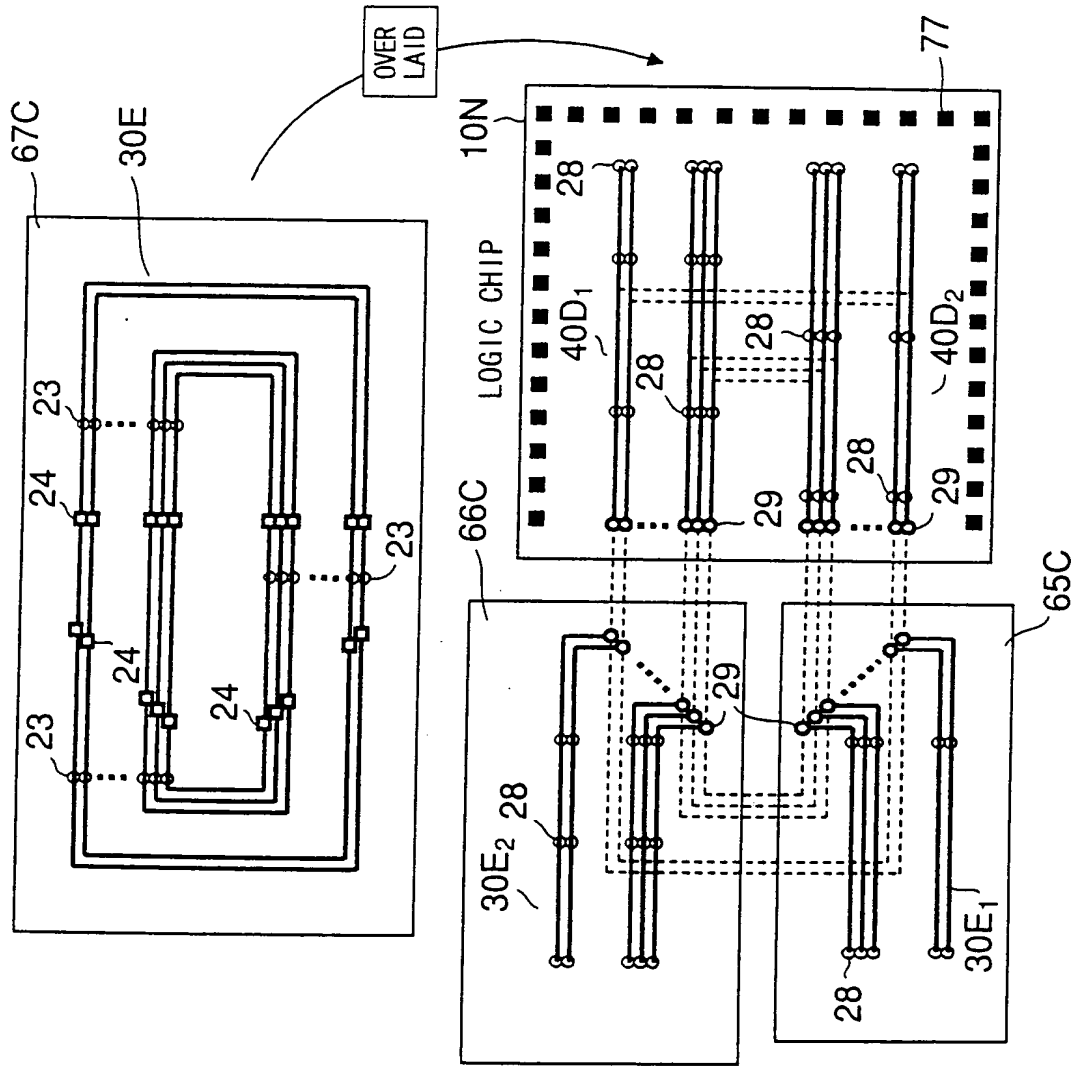


FIG. 32

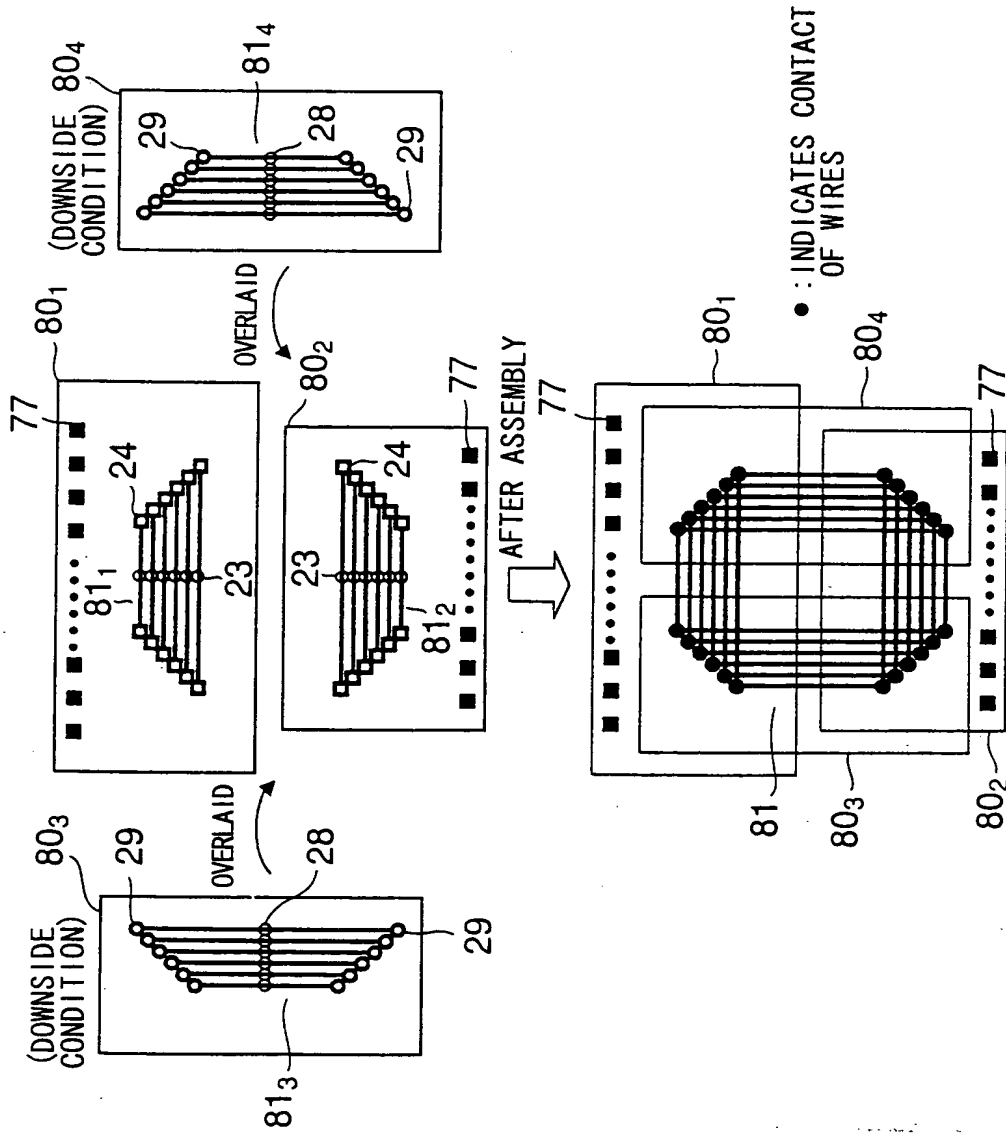


FIG. 33

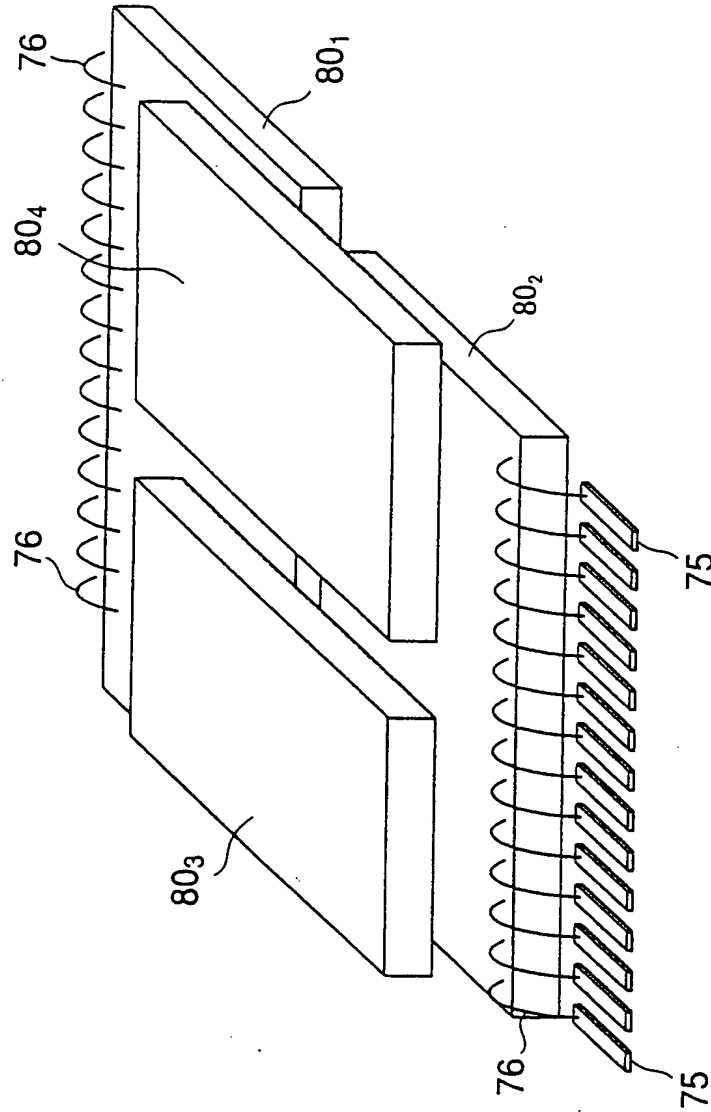
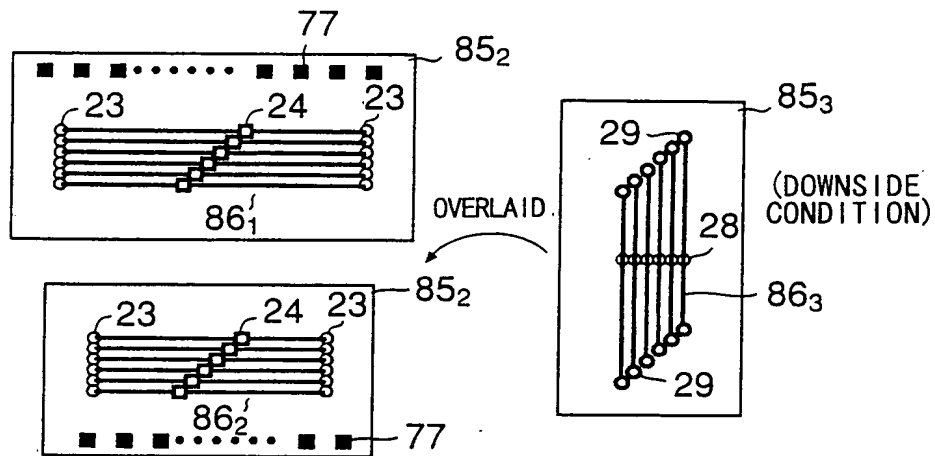


FIG. 34A



AFTER ASSEMBLY

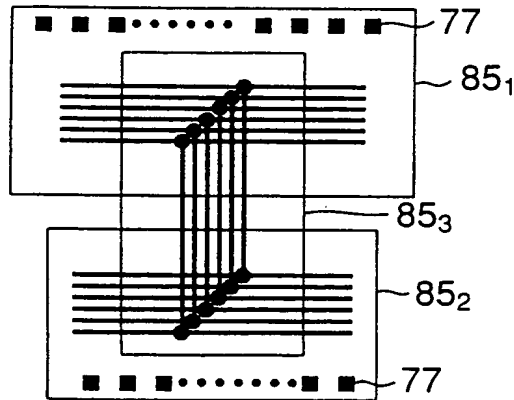


FIG. 34B

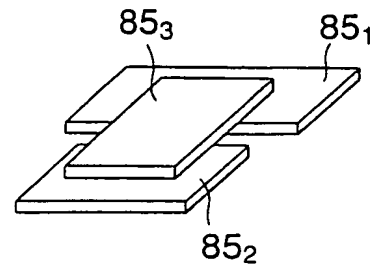


FIG.35

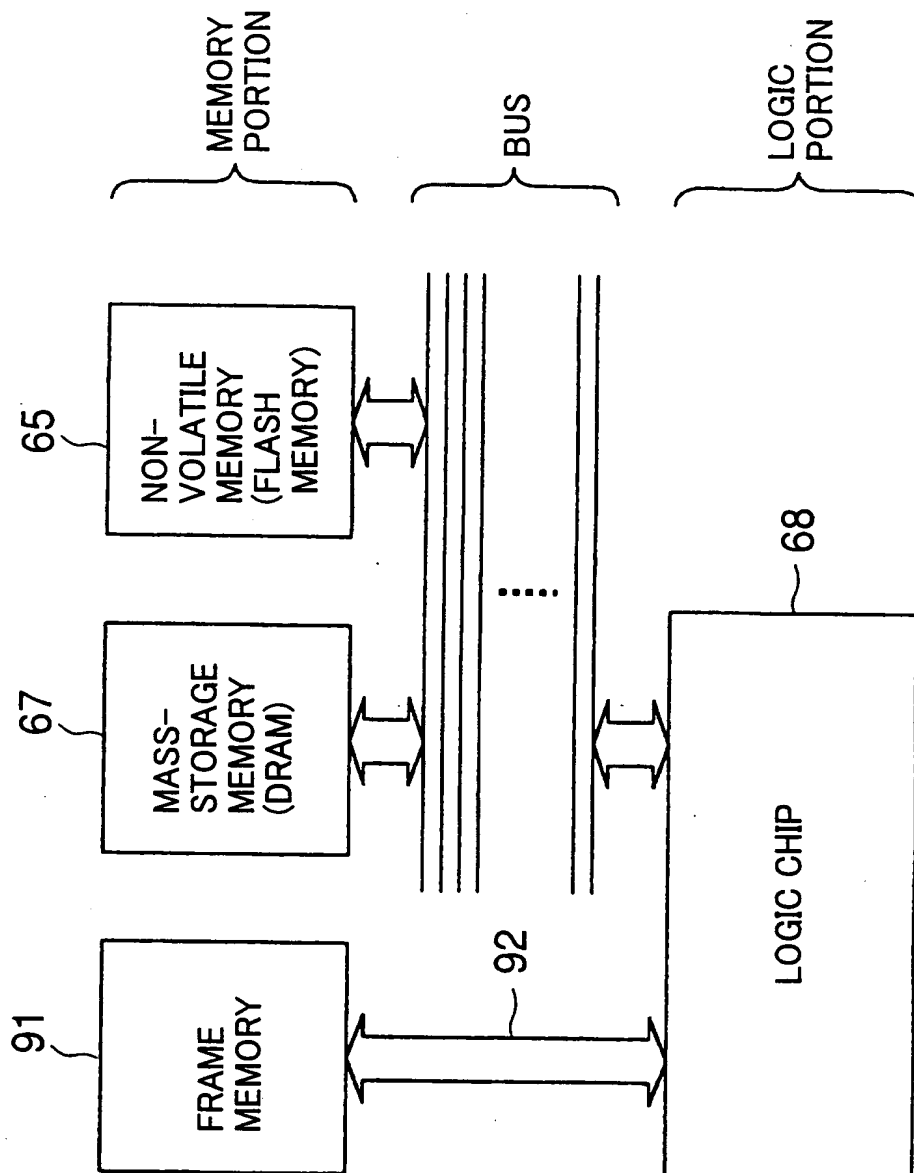


FIG. 36

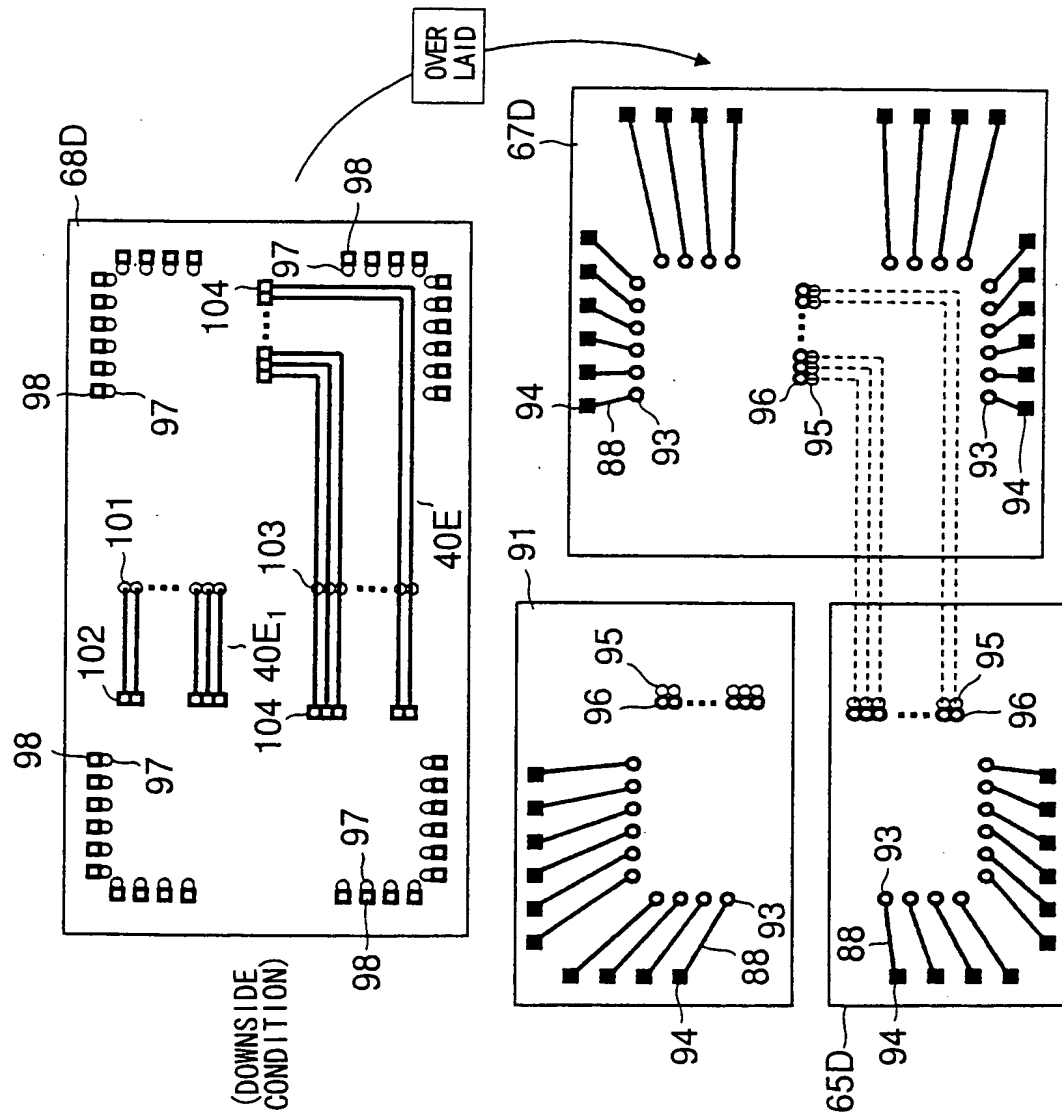


FIG.37

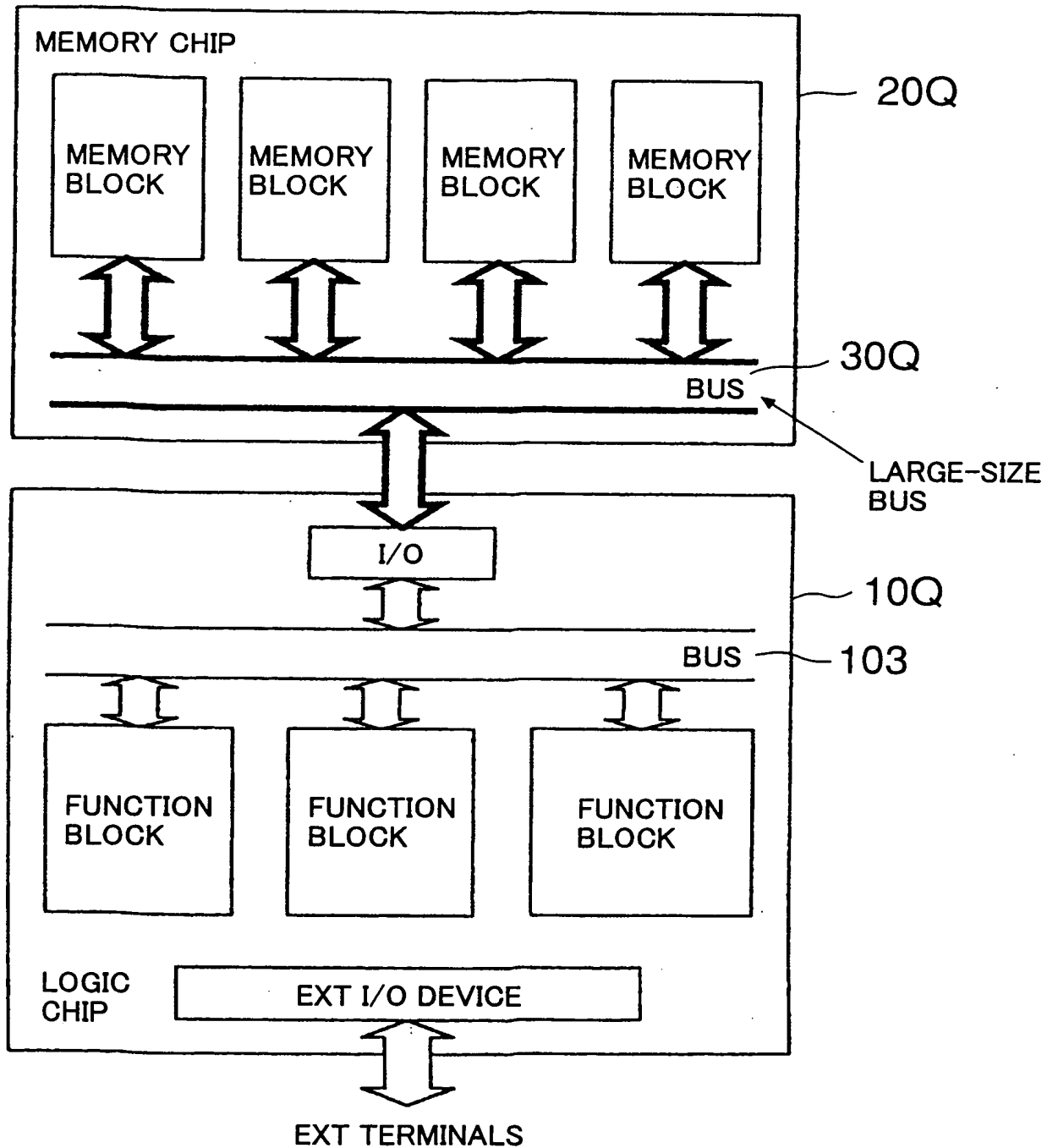


FIG.38

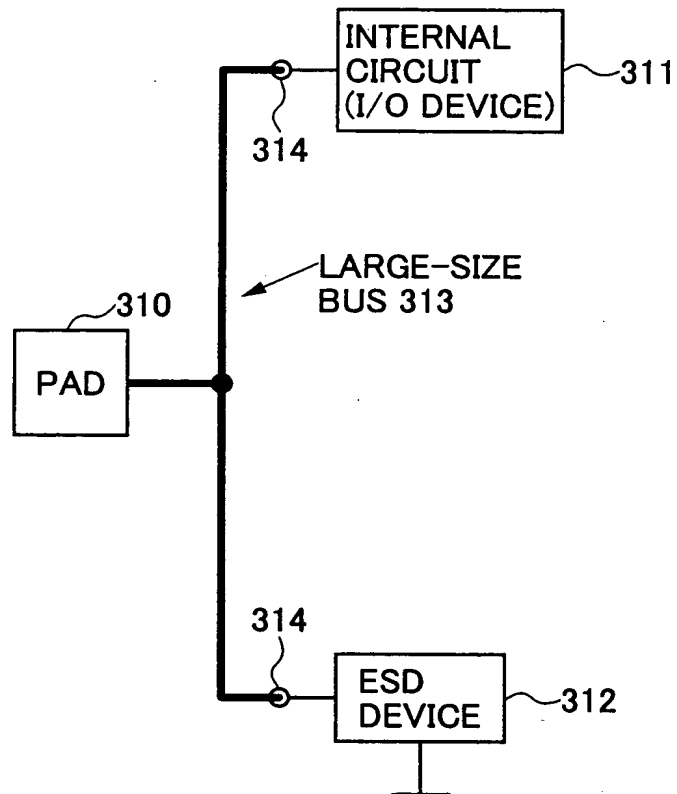


FIG. 39

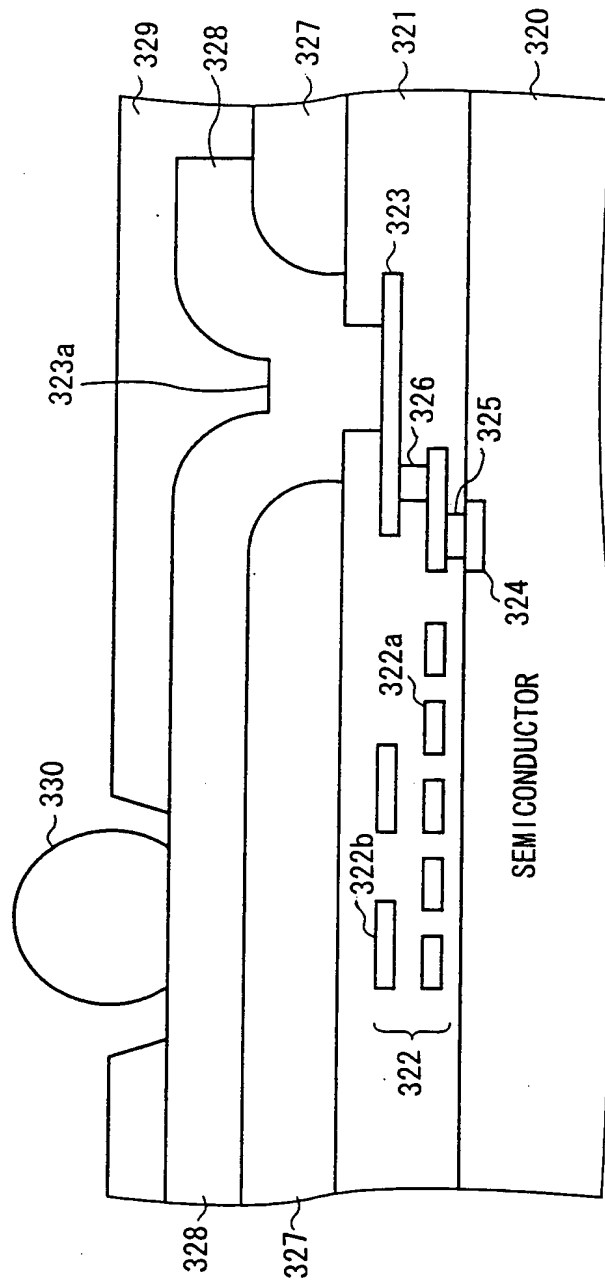


FIG.40

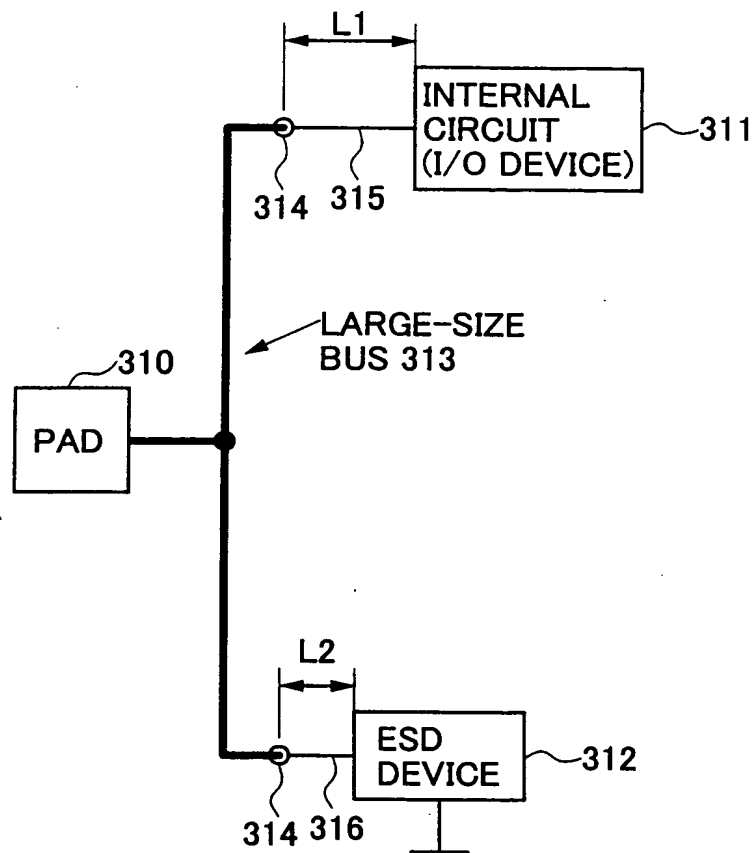


FIG.41

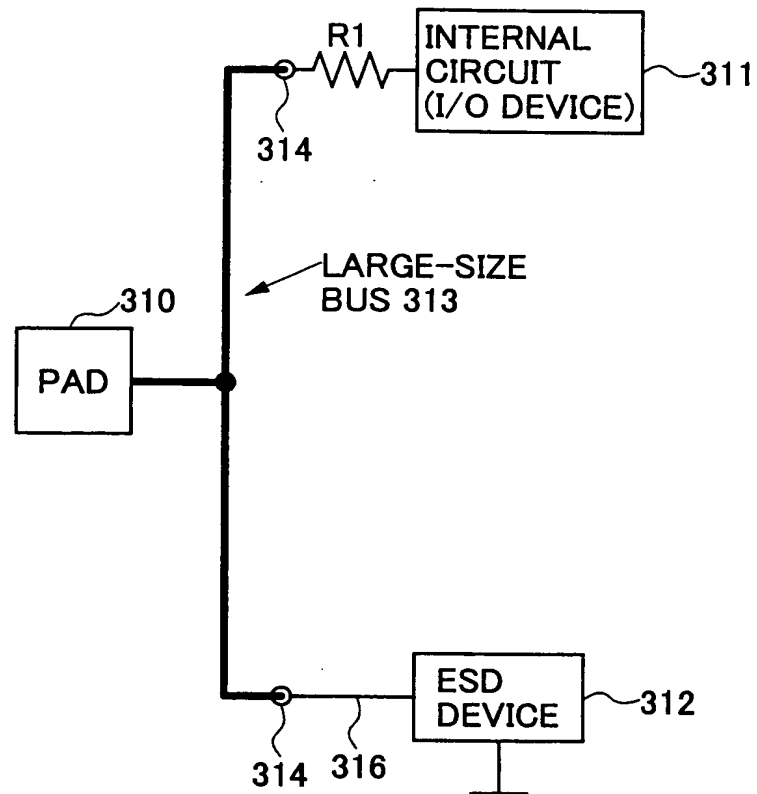


FIG.42

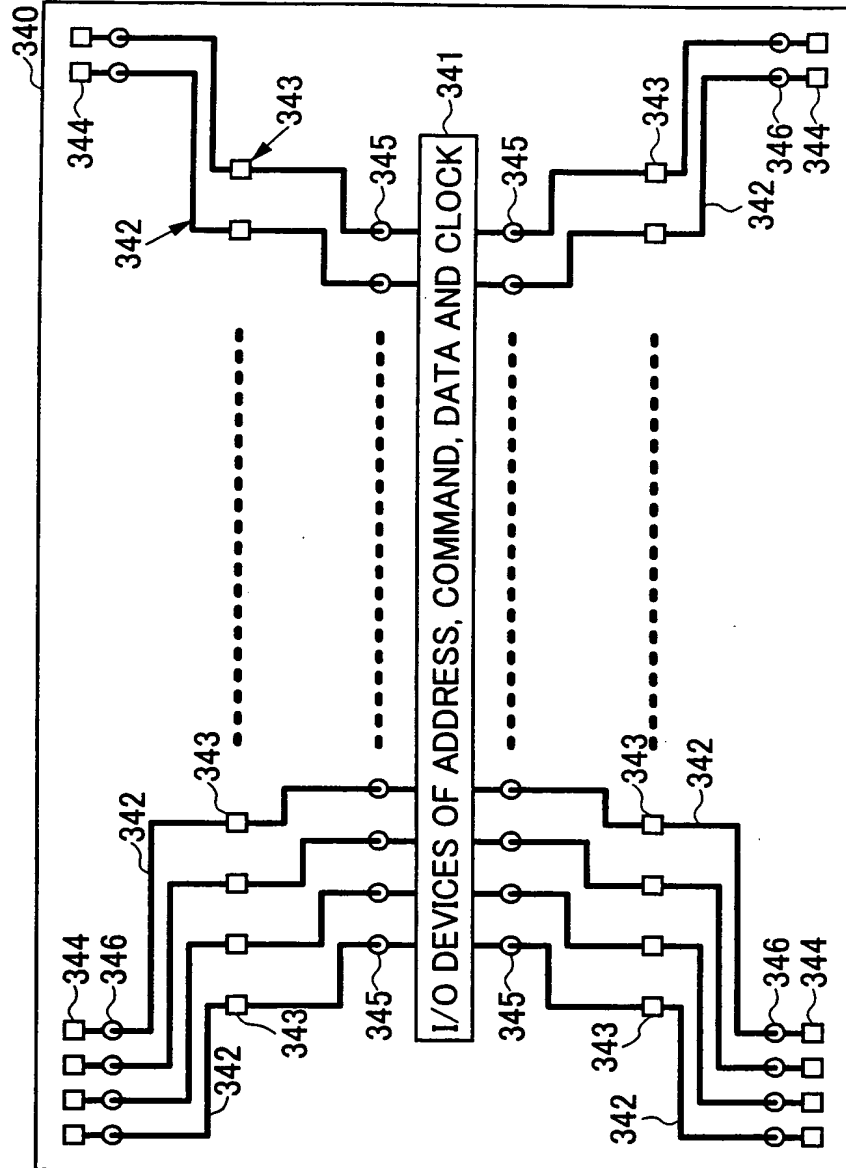


FIG.43

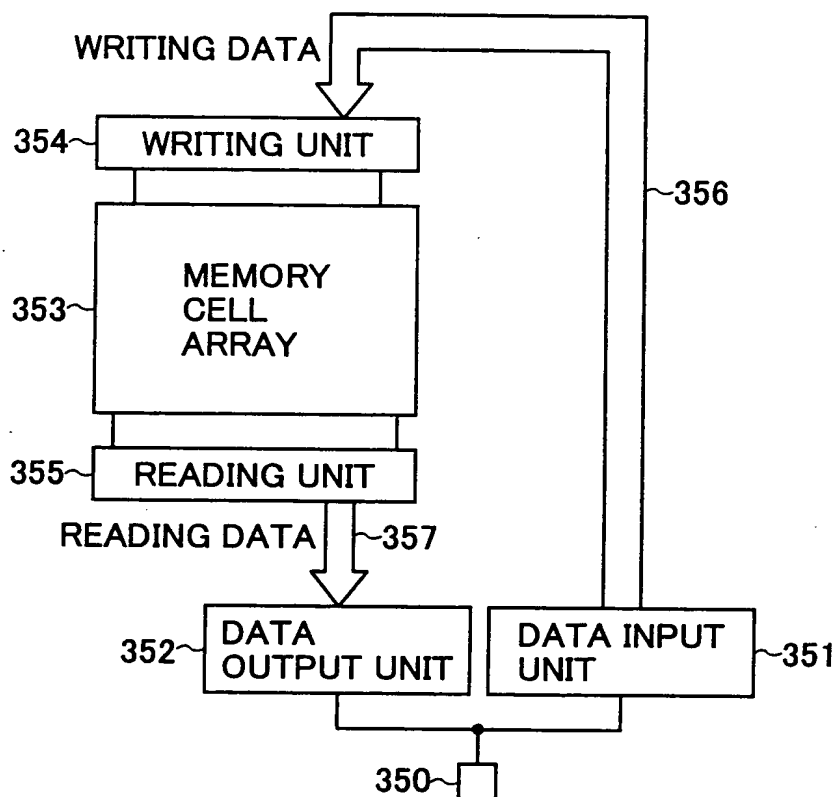


FIG.44A

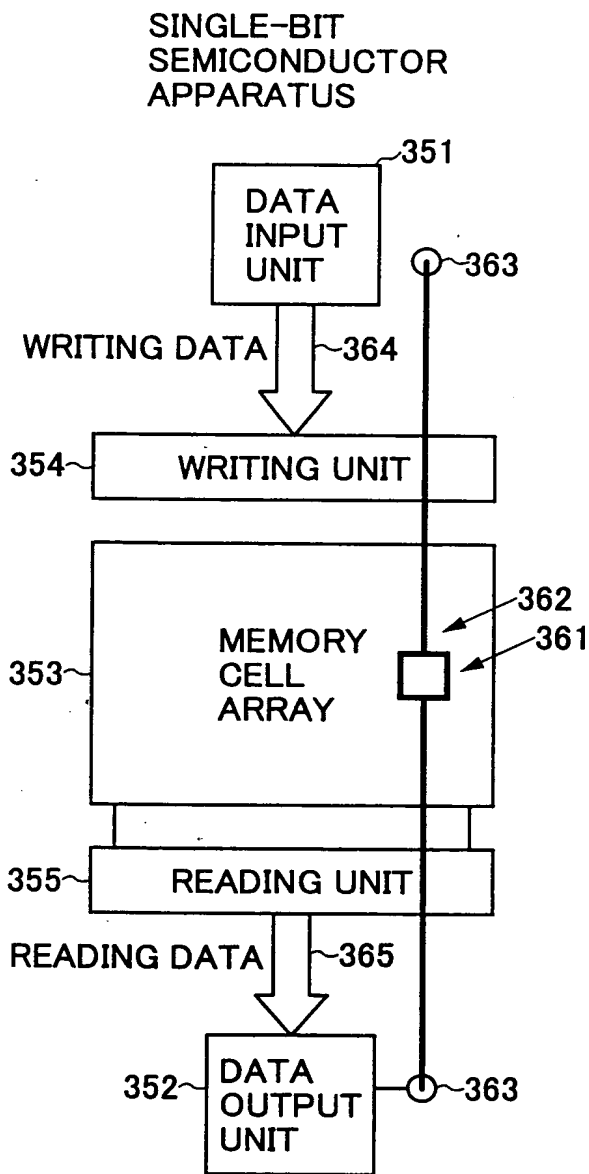


FIG.44B

